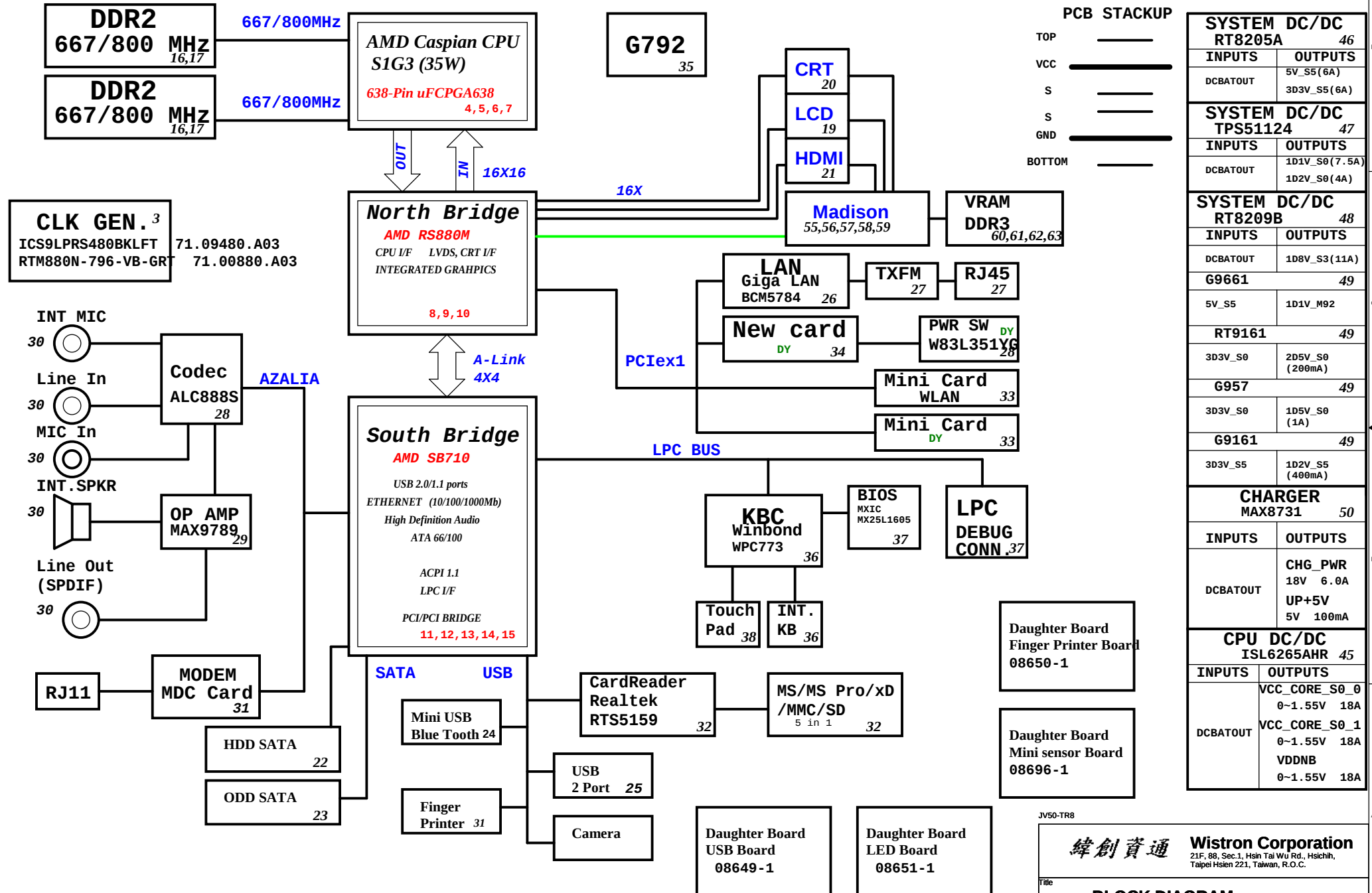


JV50-TR_8VRAM Block Diagram

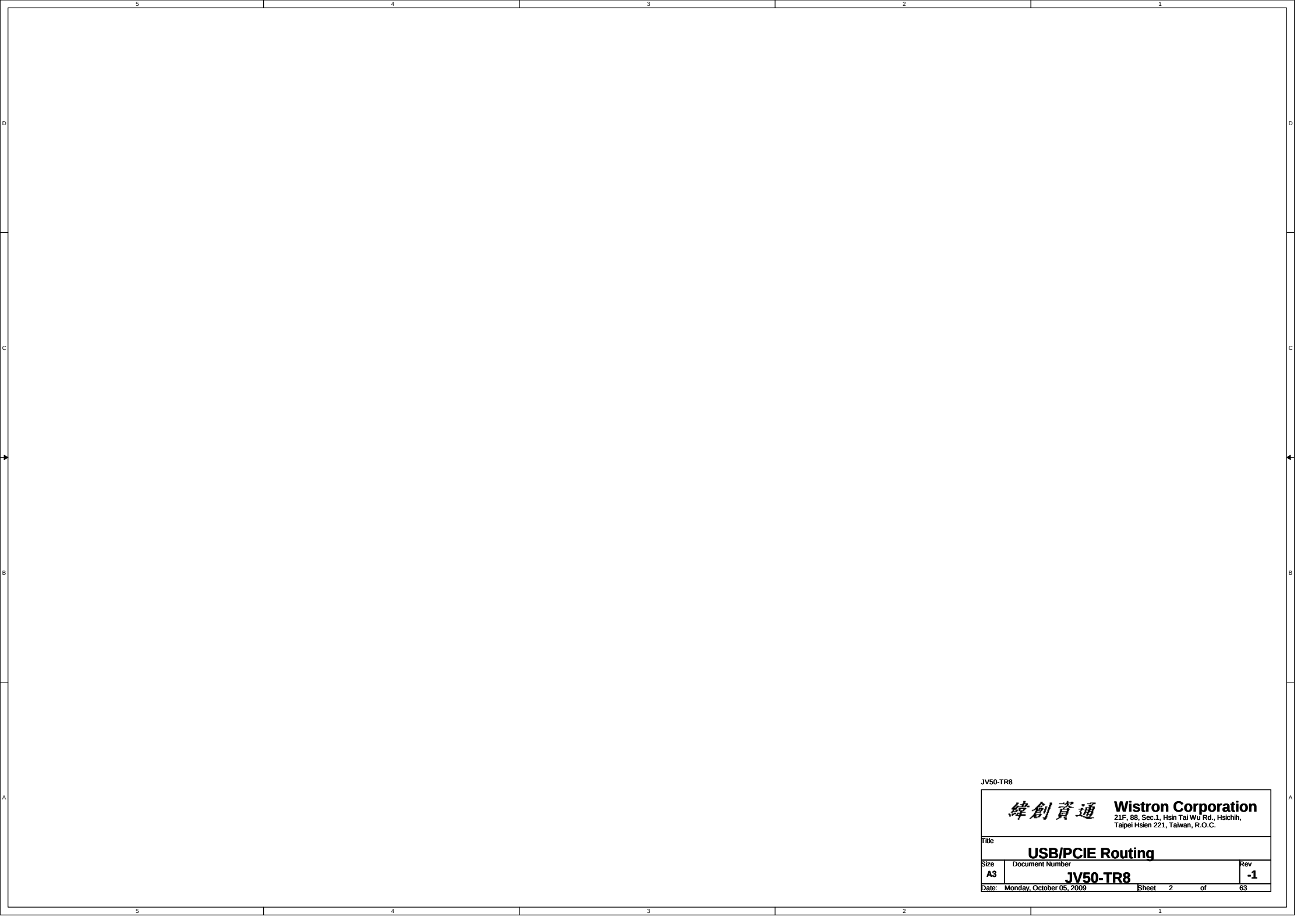
Project code: 91.4FN01.001
PCB P/N : 48.4FN02.001
REVISION : 09927-1



PCB STACKUP

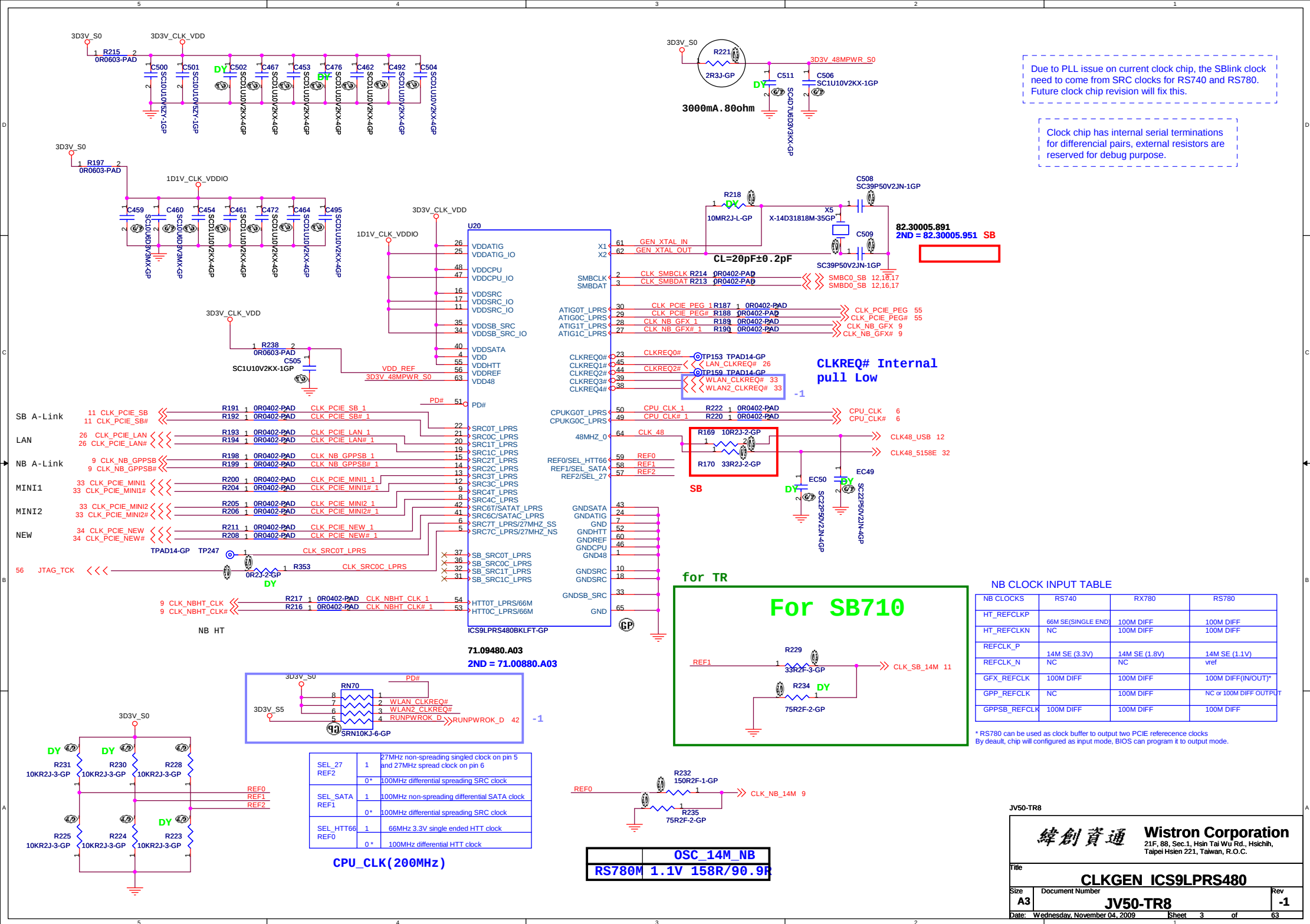
TOP	_____
VCC	_____
S	_____
S	_____
GND	_____
BOTTOM	_____

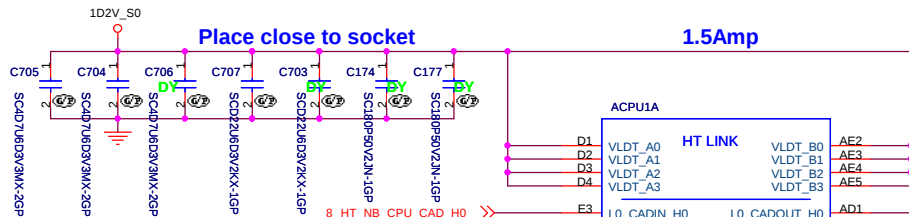
SYSTEM DC/DC RT8205A 46	
INPUTS	OUTPUTS
DCBATOUT	5V_S5(6A)
	3D3V_S5(6A)
SYSTEM DC/DC TPS51124 47	
INPUTS	OUTPUTS
DCBATOUT	1D1V_S0(7.5A)
	1D2V_S0(4A)
SYSTEM DC/DC RT8209B 48	
INPUTS	OUTPUTS
DCBATOUT	1D8V_S3(11A)
	5V_S5
	1D1V_M92
	3D3V_S0
	2D5V_S0(200mA)
	G957
	3D3V_S0
	1D5V_S0(1A)
	G9161
	3D3V_S5
	1D2V_S5(400mA)
CHARGER MAX8731 50	
INPUTS	OUTPUTS
DCBATOUT	CHG_PWR
	18V 6.0A
	UP+5V
	5V 100mA
CPU DC/DC ISL6265AHR 45	
INPUTS	OUTPUTS
DCBATOUT	VCC_CORE_S0_0
	0~1.55V 18A
	VCC_CORE_S0_1
	0~1.55V 18A
	VDDNB
	0~1.55V 18A



JV50-TR8

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
USB/PCIE Routing		
Size	Document Number	Rev
A3	JV50-TR8	-1
Date:	Monday, October 05, 2009	Sheet 2 of 63

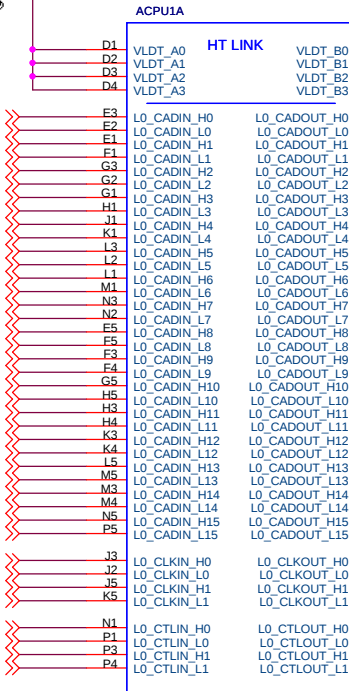




State	Specification	Notes	ZM200100M2303
S0.C0.Px	Tcase Max	3	TBD
	NB COF	1	400 MHz
	VID_VDDNB Min	2	0.950 V
	VID_VDDNB Max	2	0.950 V
	Startup P-state		S0.C0.P7
S0.C0.P0	CPU COF	1	2000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	IDD Max	3	TBD
S0.C0.P1	CPU COF	1	1800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1500 MHz
S0.C0.P2	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1300 MHz
	TDP	3	TBD
S0.C0.P3	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
S0.C0.P4	VID_VDD Max	2	1.125 V
	CPU COF	1	800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
S0.C0.P5	CPU COF	1	500 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
S0.C0.P6	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
S0.C0.P7	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V

8 HT_NB_CPU_CAD_H0
8 HT_NB_CPU_CAD_L0
8 HT_NB_CPU_CAD_H1
8 HT_NB_CPU_CAD_L1
8 HT_NB_CPU_CAD_H2
8 HT_NB_CPU_CAD_L2
8 HT_NB_CPU_CAD_H3
8 HT_NB_CPU_CAD_L3
8 HT_NB_CPU_CAD_H4
8 HT_NB_CPU_CAD_L4
8 HT_NB_CPU_CAD_H5
8 HT_NB_CPU_CAD_L5
8 HT_NB_CPU_CAD_H6
8 HT_NB_CPU_CAD_L6
8 HT_NB_CPU_CAD_H7
8 HT_NB_CPU_CAD_L7
8 HT_NB_CPU_CAD_H8
8 HT_NB_CPU_CAD_L8
8 HT_NB_CPU_CAD_H9
8 HT_NB_CPU_CAD_L9
8 HT_NB_CPU_CAD_H10
8 HT_NB_CPU_CAD_L10
8 HT_NB_CPU_CAD_H11
8 HT_NB_CPU_CAD_L11
8 HT_NB_CPU_CAD_H12
8 HT_NB_CPU_CAD_L12
8 HT_NB_CPU_CAD_H13
8 HT_NB_CPU_CAD_L13
8 HT_NB_CPU_CAD_H14
8 HT_NB_CPU_CAD_L14
8 HT_NB_CPU_CAD_H15
8 HT_NB_CPU_CAD_L15

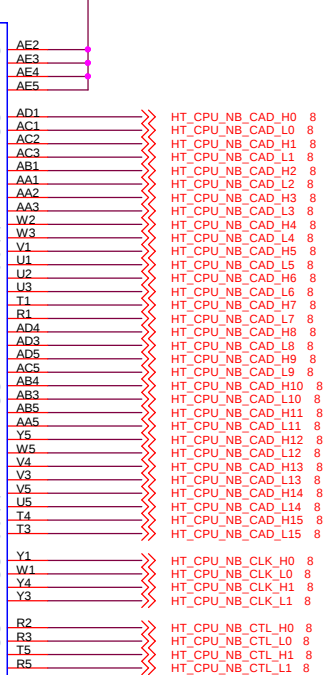
8 HT_NB_CPU_CLK_H0
8 HT_NB_CPU_CLK_L0
8 HT_NB_CPU_CLK_H1
8 HT_NB_CPU_CLK_L1
8 HT_NB_CPU_CTL_H0
8 HT_NB_CPU_CTL_L0
8 HT_NB_CPU_CTL_H1
8 HT_NB_CPU_CTL_L1



SKT-CPU638P,DANUB
62.10055.111

2ND = 62.10055.251

SKT - BGA638H176



JV50-TR8

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

CPU HT LINK I/F (1/4)

Size

A3

Document Number

JV50-TR8

Date

Monday, October 26, 2009

Sheet

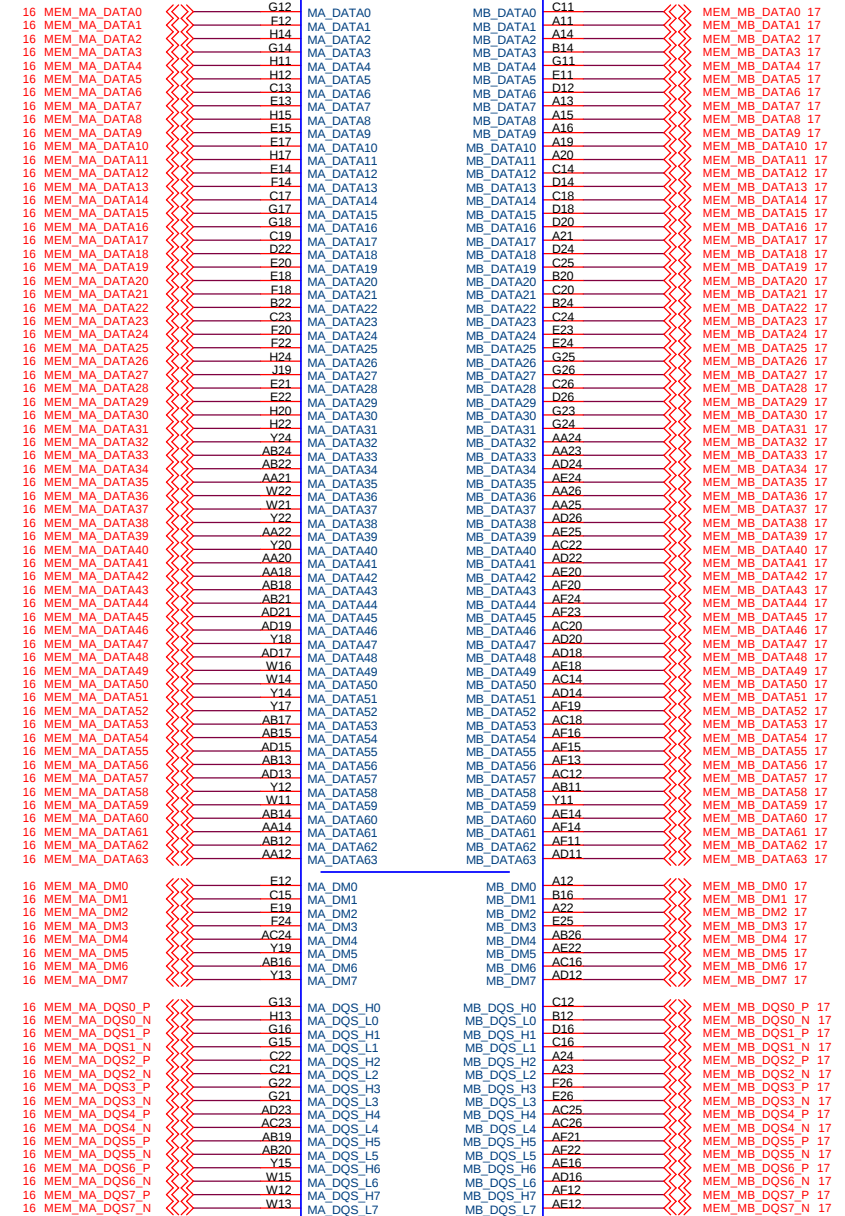
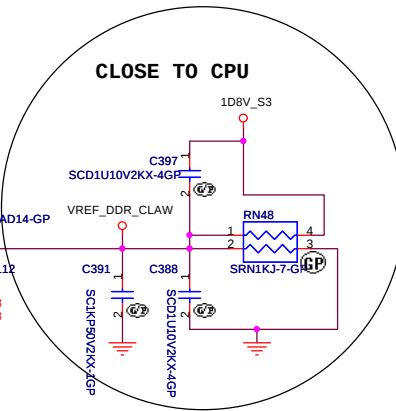
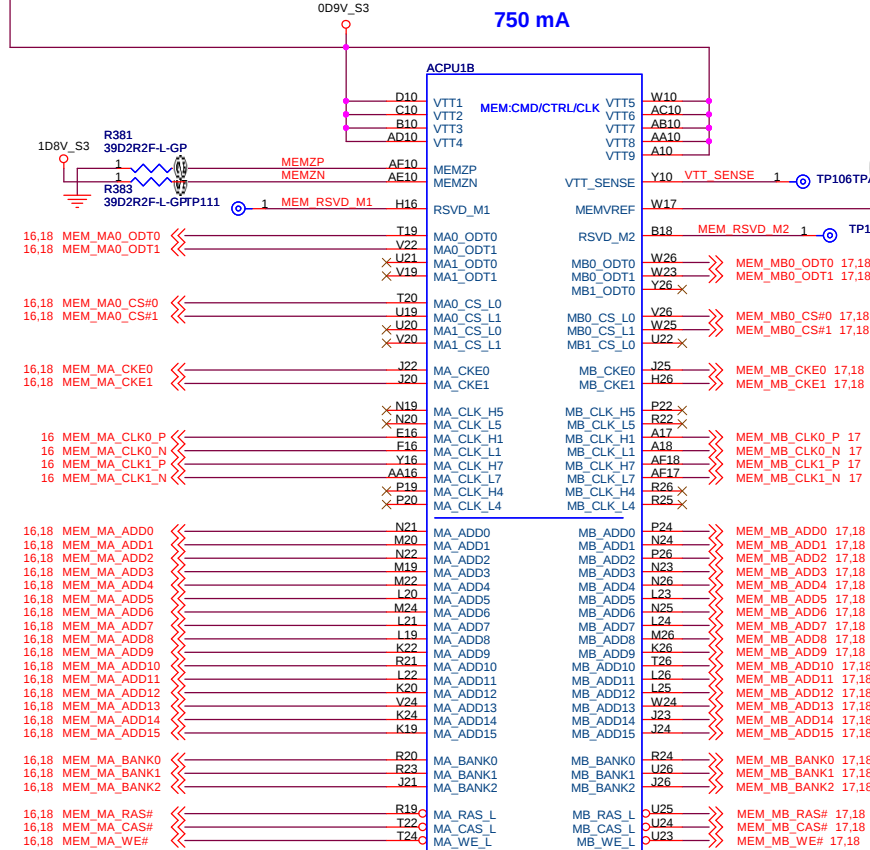
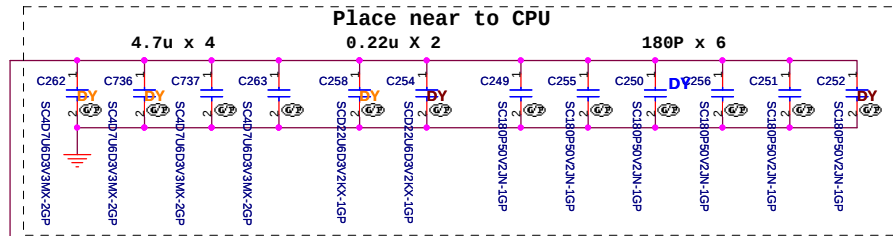
4

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63

Rev

-1



SKT-CPU638P.DANUB

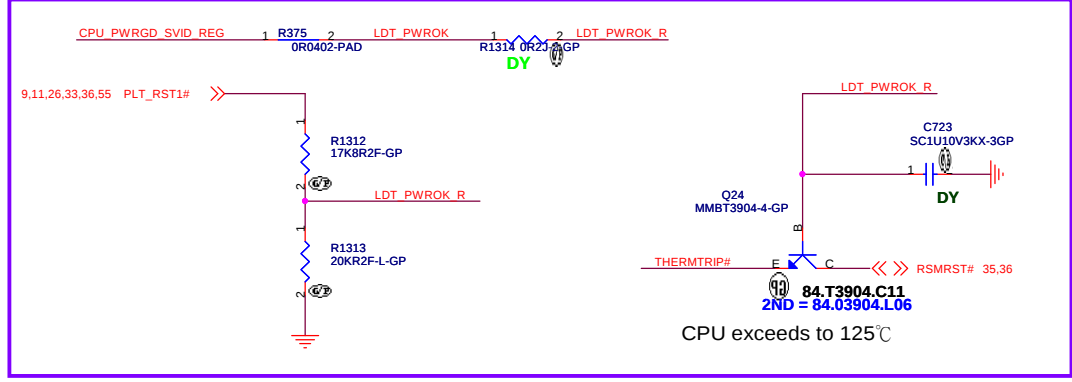
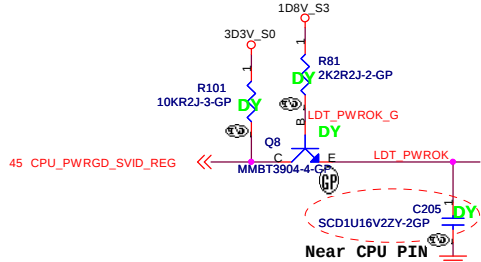
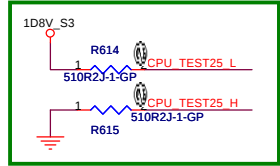
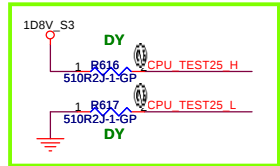
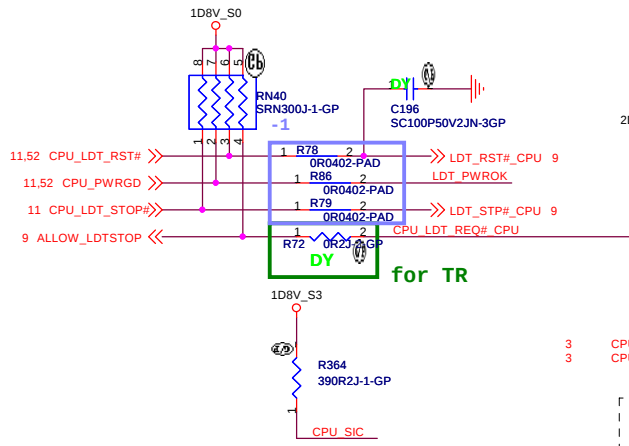
62.10055.111

JV50-TR8

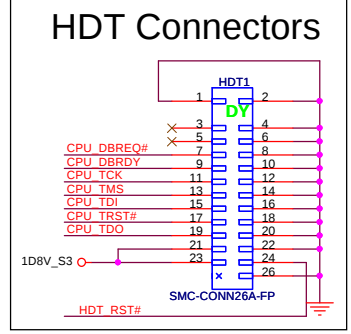
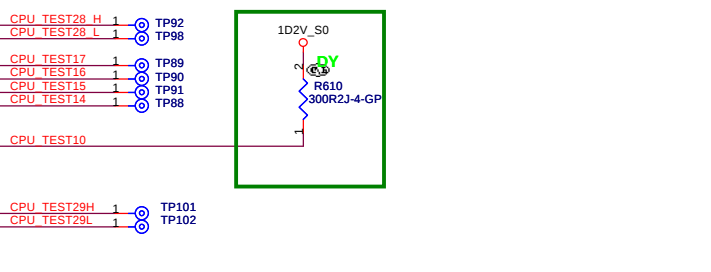
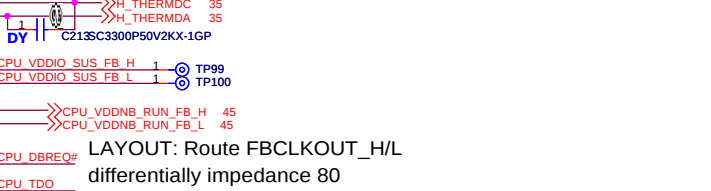
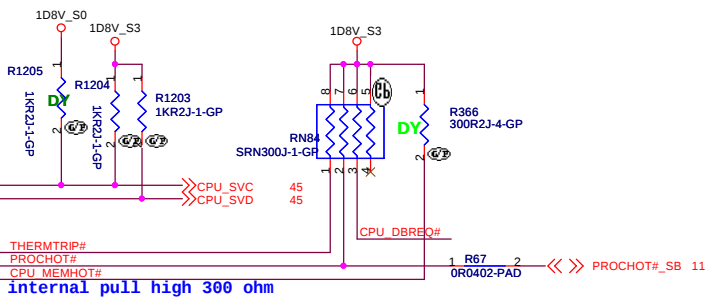
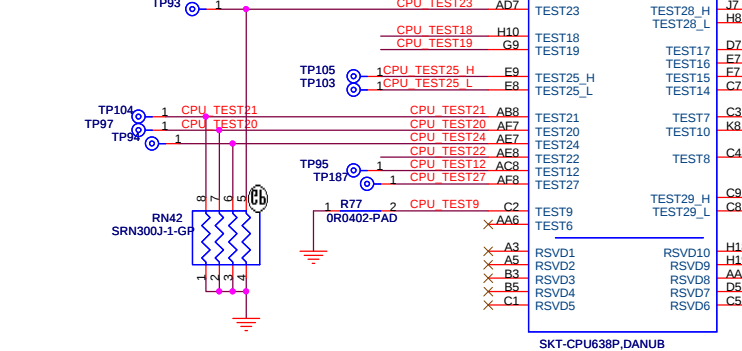
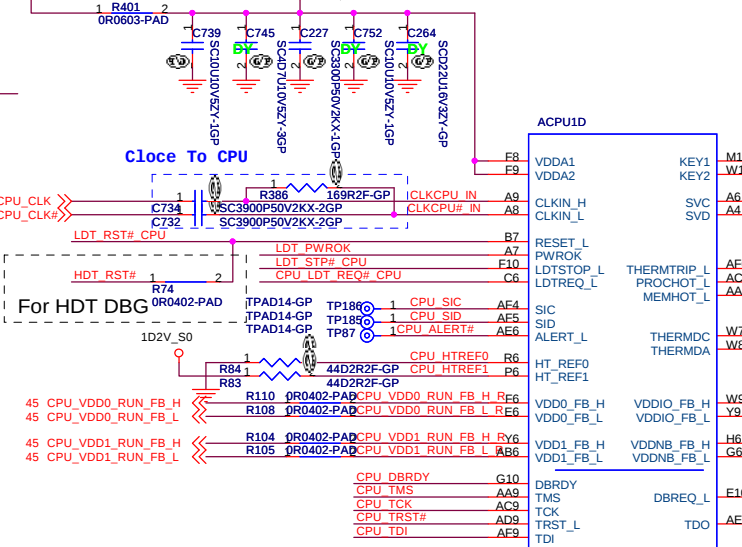
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			CPU DDR (2/4)		
Size			Document Number		
A3			JV50-TR8		
Date:			Monday, October 26, 2009		
Sheet			5		
of			63		
Rev			-1		

The Processor has reached a preset maximum operating temperature. 100°C
I=Active HTC
O=FAN



IF 0 ohm IS NOT GOOD ENOUGH, TRY 68.00082.491
LYAOUT:ROUTE VDDA TRACE APPROX.
50mils WIDE(USE 2X25 mil TRACES TO
EXIT BALL FIELD) AND 500 mils LONG.



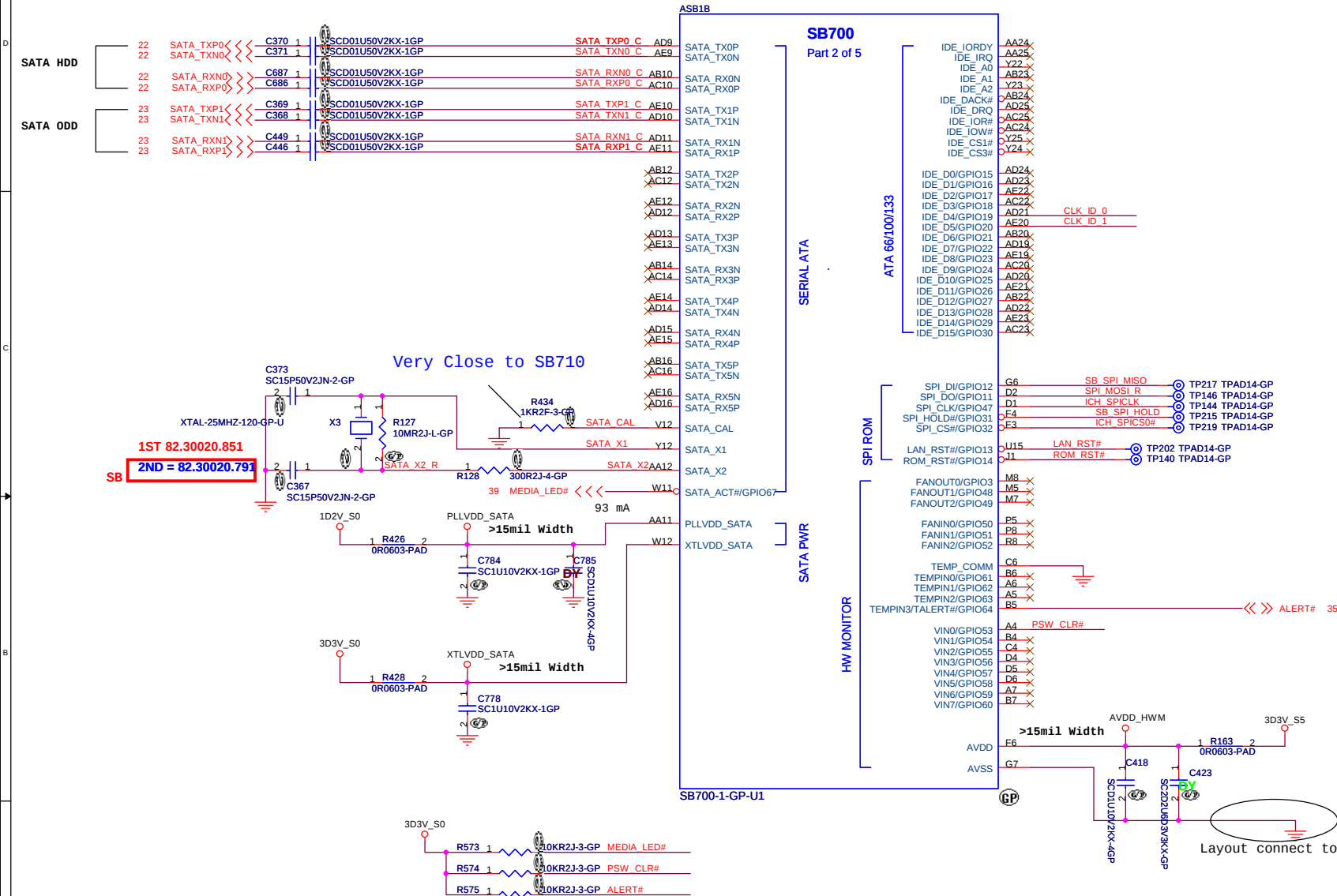




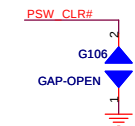
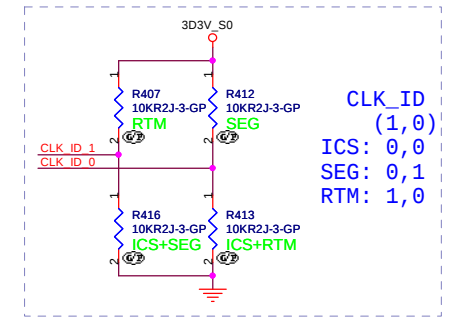




PLACE SATA AC DECOUPLING
CAPS CLOSE TO SB710



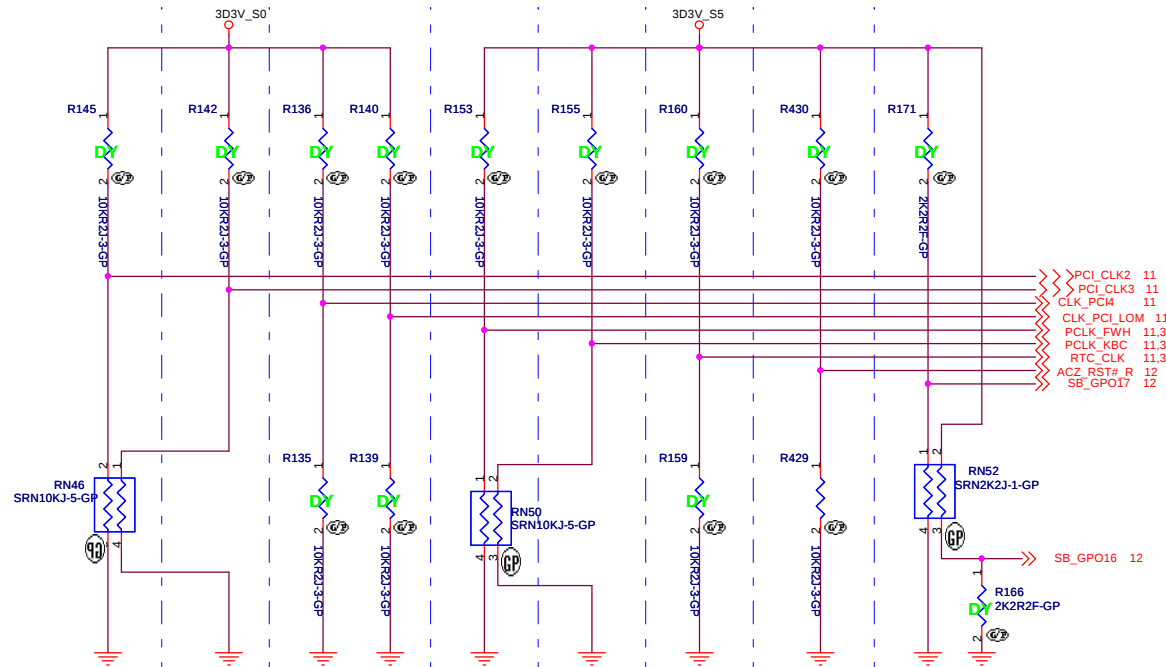
Dummy CKG select



Layout connect to Cap then GND

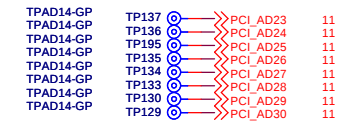
REQUIRED STRAPS

REQUIRED SYSTEM STRAPS



NOTE: SB700 HAS INTERNAL 15K PULL UP RESISTOR FOR RTCCLK

DEBUG STRAPS



	PCI_AD28	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23	PCI_AD30 PCI_AD29
PULL HIGH	USE LONG RESET (DEFAULT)	USE PCI PLL (DEFAULT)	USE ACPI BCLK (DEFAULT)	USE IDE PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Reserved (DEFAULT)	Reserved
PULL LOW	USE SHORT RESET	BYPASS PCI PLL	BYPASS ACPI BCLK	BYPASS IDE PLL	USE EEPROM PCIE STRAPS	Reserved	

Note: SB700 has 15K internal PU FOR PCI_AD[30:23]

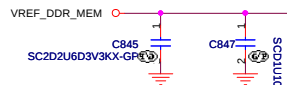
JV50-TR8

5.18 MEM_MA_ADD0 >> 102 A0
5.18 MEM_MA_ADD1 >> 101 A1
5.18 MEM_MA_ADD2 >> 100 A2
5.18 MEM_MA_ADD3 >> 99 A3
5.18 MEM_MA_ADD4 >> 98 A4
5.18 MEM_MA_ADD5 >> 97 A5
5.18 MEM_MA_ADD6 >> 96 A6
5.18 MEM_MA_ADD7 >> 95 A7
5.18 MEM_MA_ADD8 >> 94 A8
5.18 MEM_MA_ADD9 >> 93 A9
5.18 MEM_MA_ADD10 >> 92 A10/AP
5.18 MEM_MA_ADD11 >> 91 A11
5.18 MEM_MA_ADD12 >> 90 A12
5.18 MEM_MA_ADD13 >> 89 A13
5.18 MEM_MA_ADD14 >> 88 A14
5.18 MEM_MA_ADD15 >> 87 A15
5.18 MEM_MA_BANK2 >> 107 BA0
5.18 MEM_MA_BANK0 >> 106 BA1
5.18 MEM_MA_BANK1 >> 105 BA2

5 MEM_MA_DATA0 >> 5 DQ0
5 MEM_MA_DATA1 >> 17 DQ1
5 MEM_MA_DATA2 >> 19 DQ2
5 MEM_MA_DATA3 >> 4 DQ3
5 MEM_MA_DATA4 >> 6 DQ4
5 MEM_MA_DATA5 >> 14 DQ5
5 MEM_MA_DATA6 >> 16 DQ6
5 MEM_MA_DATA7 >> 23 DQ7
5 MEM_MA_DATA8 >> 25 DQ8
5 MEM_MA_DATA9 >> 26 DQ9
5 MEM_MA_DATA10 >> 37 DQ10
5 MEM_MA_DATA11 >> 36 DQ11
5 MEM_MA_DATA12 >> 20 DQ12
5 MEM_MA_DATA13 >> 22 DQ13
5 MEM_MA_DATA14 >> 38 DQ14
5 MEM_MA_DATA15 >> 39 DQ15
5 MEM_MA_DATA16 >> 43 DQ16
5 MEM_MA_DATA17 >> 45 DQ17
5 MEM_MA_DATA18 >> 55 DQ18
5 MEM_MA_DATA19 >> 57 DQ19
5 MEM_MA_DATA20 >> 44 DQ20
5 MEM_MA_DATA21 >> 46 DQ21
5 MEM_MA_DATA22 >> 58 DQ22
5 MEM_MA_DATA23 >> 61 DQ23
5 MEM_MA_DATA24 >> 62 DQ24
5 MEM_MA_DATA25 >> 63 DQ25
5 MEM_MA_DATA26 >> 73 DQ26
5 MEM_MA_DATA27 >> 75 DQ27
5 MEM_MA_DATA28 >> 62 DQ28
5 MEM_MA_DATA29 >> 64 DQ29
5 MEM_MA_DATA30 >> 74 DQ30
5 MEM_MA_DATA31 >> 123 DQ31
5 MEM_MA_DATA32 >> 125 DQ32
5 MEM_MA_DATA33 >> 126 DQ33
5 MEM_MA_DATA34 >> 137 DQ34
5 MEM_MA_DATA35 >> 124 DQ35
5 MEM_MA_DATA36 >> 126 DQ36
5 MEM_MA_DATA37 >> 134 DQ37
5 MEM_MA_DATA38 >> 136 DQ38
5 MEM_MA_DATA39 >> 141 DQ39
5 MEM_MA_DATA40 >> 143 DQ40
5 MEM_MA_DATA41 >> 144 DQ41
5 MEM_MA_DATA42 >> 151 DQ42
5 MEM_MA_DATA43 >> 140 DQ43
5 MEM_MA_DATA44 >> 142 DQ44
5 MEM_MA_DATA45 >> 140 DQ45
5 MEM_MA_DATA46 >> 152 DQ46
5 MEM_MA_DATA47 >> 154 DQ47
5 MEM_MA_DATA48 >> 157 DQ48
5 MEM_MA_DATA49 >> 159 DQ49
5 MEM_MA_DATA50 >> 173 DQ50
5 MEM_MA_DATA51 >> 175 DQ51
5 MEM_MA_DATA52 >> 158 DQ52
5 MEM_MA_DATA53 >> 160 DQ53
5 MEM_MA_DATA54 >> 174 DQ54
5 MEM_MA_DATA55 >> 176 DQ55
5 MEM_MA_DATA56 >> 179 DQ56
5 MEM_MA_DATA57 >> 181 DQ57
5 MEM_MA_DATA58 >> 189 DQ58
5 MEM_MA_DATA59 >> 191 DQ59
5 MEM_MA_DATA60 >> 180 DQ60
5 MEM_MA_DATA61 >> 182 DQ61
5 MEM_MA_DATA62 >> 192 DQ62
5 MEM_MA_DATA63 >> 194 DQ63

5 MEM_MA_DQS0_N >> 11 DQS0#
5 MEM_MA_DQS1_N >> 29 DQS1#
5 MEM_MA_DQS2_N >> 49 DQS2#
5 MEM_MA_DQS3_N >> 68 DQS3#
5 MEM_MA_DQS4_N >> 122 DQS4#
5 MEM_MA_DQS5_N >> 146 DQS5#
5 MEM_MA_DQS6_N >> 167 DQS6#
5 MEM_MA_DQS7_N >> 186 DQS7#
5 MEM_MA_DQS0_P >> 13 DQS0#
5 MEM_MA_DQS1_P >> 31 DQS1#
5 MEM_MA_DQS2_P >> 51 DQS2#
5 MEM_MA_DQS3_P >> 70 DQS3#
5 MEM_MA_DQS4_P >> 131 DQS4#
5 MEM_MA_DQS5_P >> 148 DQS5#
5 MEM_MA_DQS6_P >> 169 DQS6#
5 MEM_MA_DQS7_P >> 188 DQS7#

5.18 MEM_MA0_ODT0 >> 114 OTD0
5.18 MEM_MA0_ODT1 >> 119 OTD1



Place C2.2uF and 0.1uF < 500mils from DDR connector

ADIMM2
A0
A1
A2
A3
A4
A5
A6
A7
A8
A9
A10/AP
A11
A12
A13
A14
A15
A16/BA2
BA0
BA1

NORMAL TYPE

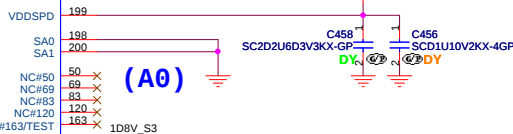
(A0)
50 X
69 X
83 X
120 X
163 X
1D8V_S3

VDD 81
VDD 82
VDD 87
VDD 88
VDD 95
VDD 96
VDD 103
VDD 104
VDD 111
VDD 112
VDD 117
VDD 118
VSS 3
VSS 8
VSS 9
VSS 12
VSS 15
VSS 18
VSS 21
VSS 27
VSS 28
VSS 33
VSS 34
VSS 39
VSS 40
VSS 41
VSS 42
VSS 47
VSS 48
VSS 53
VSS 54
VSS 59
VSS 60
VSS 65
VSS 66
VSS 71
VSS 72
VSS 77
VSS 78
VSS 121
VSS 122
VSS 127
VSS 128
VSS 132
VSS 133
VSS 138
VSS 139
VSS 144
VSS 145
VSS 149
VSS 150
VSS 155
VSS 156
VSS 161
VSS 162
VSS 165
VSS 168
VSS 171
VSS 172
VSS 177
VSS 178
VSS 183
VSS 184
VSS 187
VSS 190
VSS 193
VSS 196
VSS 201
GND 201
MH2
MH1

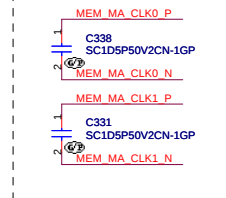
2ND = 62.10017.A41
3RD = 62.10017.G81

RAS# 108
WE# 109
CAS# 113
CS0# 110
CS1# 115
CKE0 79
CKE1 80
CK0 30
CK0# 32
CK1 164
CK1# 166
DM0 10
DM1 26
DM2 52
DM3 67
DM4 130
DM5 147
DM6 170
DM7 185
MEM_MA_RAS# 5.18
MEM_MA_WE# 5.18
MEM_MA_CAS# 5.18
MEM_MA_CS#0 5.18
MEM_MA_CS#1 5.18
MEM_MA_CKE0 5.18
MEM_MA_CKE1 5.18
MEM_MA_CLK0_P 5
MEM_MA_CLK0_N 5
MEM_MA_CLK1_P 5
MEM_MA_CLK1_N 5
MEM_MA_DM0 5
MEM_MA_DM1 5
MEM_MA_DM2 5
MEM_MA_DM3 5
MEM_MA_DM4 5
MEM_MA_DM5 5
MEM_MA_DM6 5
MEM_MA_DM7 5

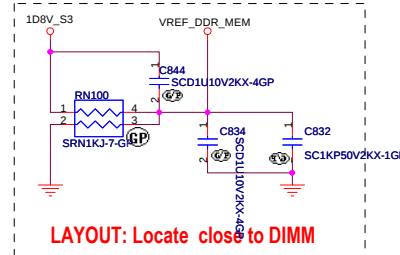
SDA 195
SCL 197
SMBD0_SB 3.12.17
SMBC0_SB 3.12.17
3D3V_S0
VDDSPD 199



PLACE CLOSE TO PROCESSOR
WITHIN 1.5 INCH



DDR_VREF

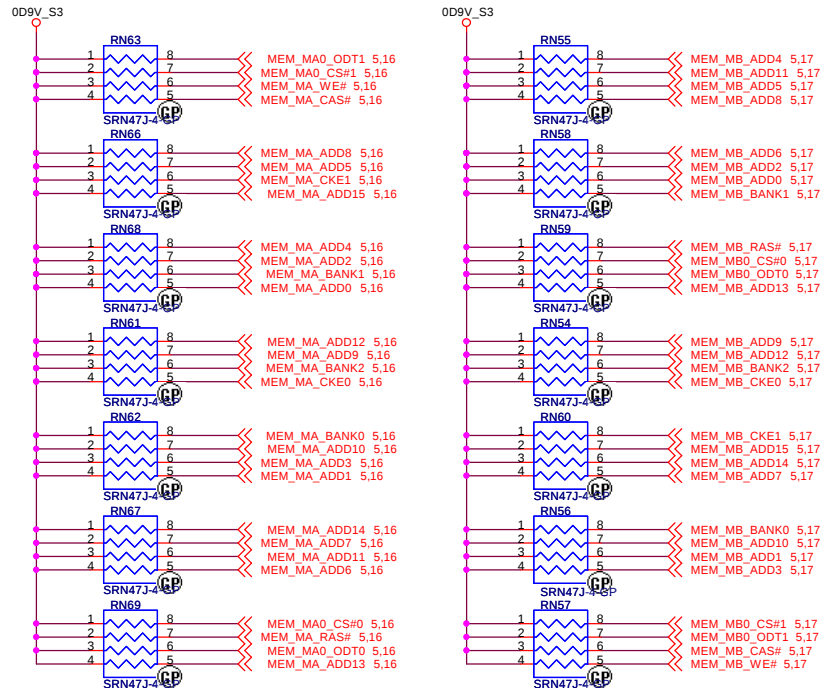


LOW 5.2 mm

JV50-TR8

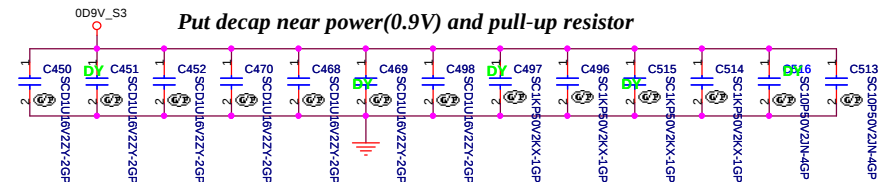
PARALLEL TERMINATION

Put decap near power(0.9V) and pull-up resistor

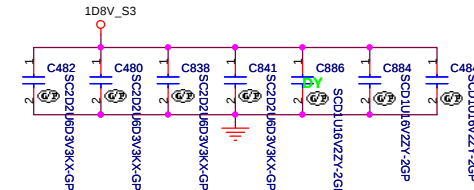


Do not share the Term resistor between the DDR address and Control Signals.

Decoupling Capacitor

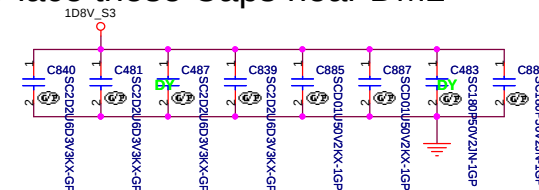


Place these Caps near DM1



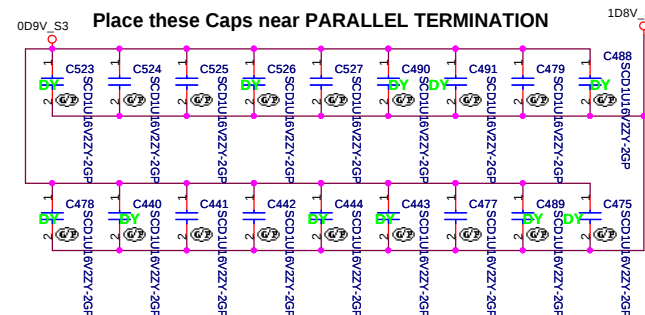
Layout Note:
Place one cap close to every 2 pullup resistors terminated to 0D9V_S3

Place these Caps near DM2



Layout Note:
Place one cap close to every 2 pullup resistors terminated to 0D9V_S3

Place these Caps near PARALLEL TERMINATION

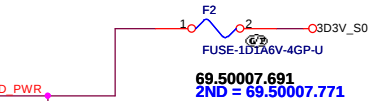
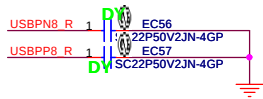
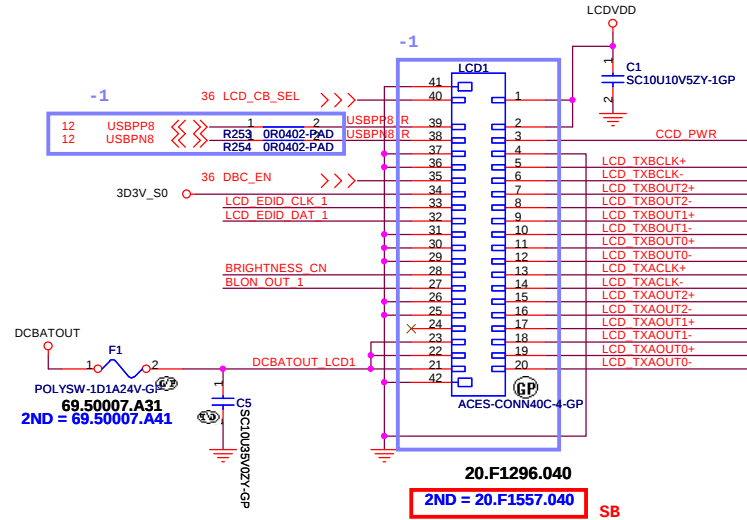


JV50-TR8

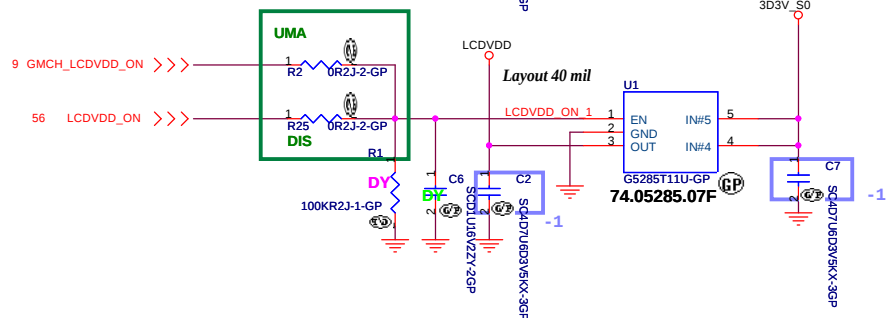
緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

Title		
DDR DAMPING & TERMINATION		
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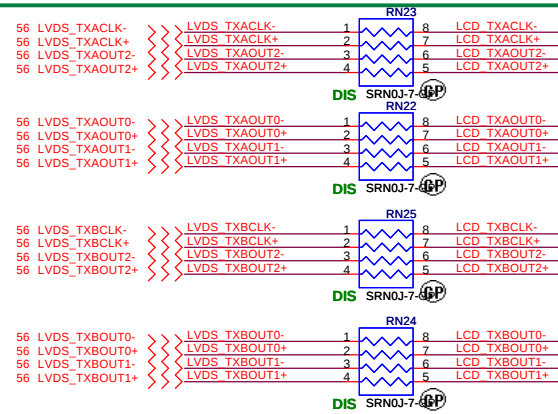
LCD/INVERTER/CCD CONN



for TR

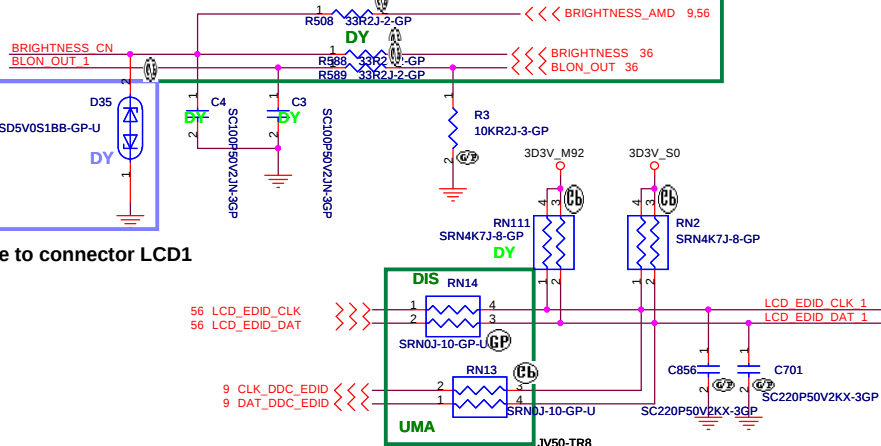
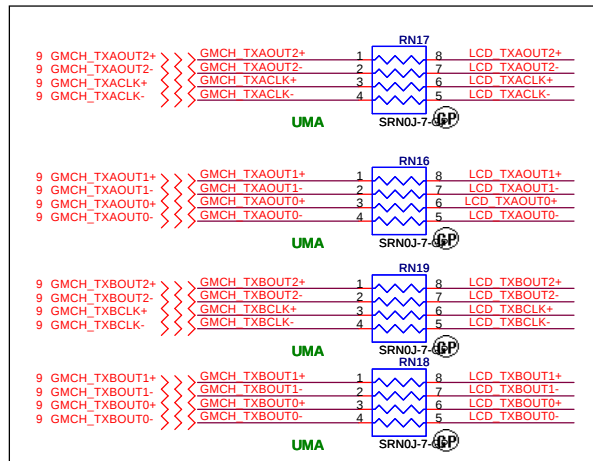


for TR

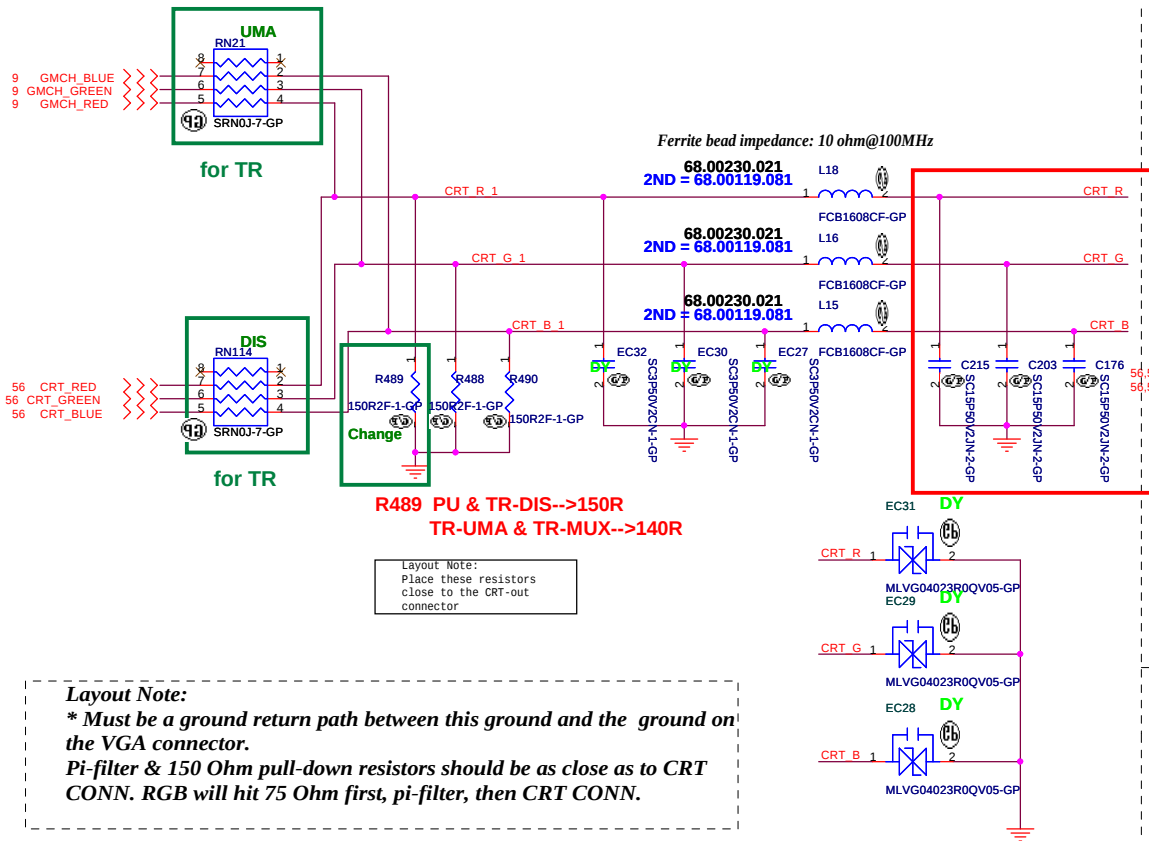


Inverter Pin	
Pin	Symbol
1	Vin
2	Vin
3	Brightness
4	BLON
5	GND
6	GND

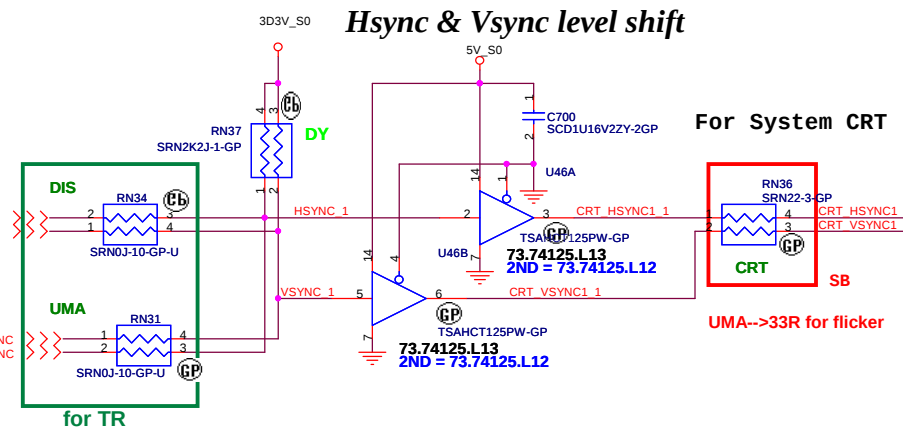
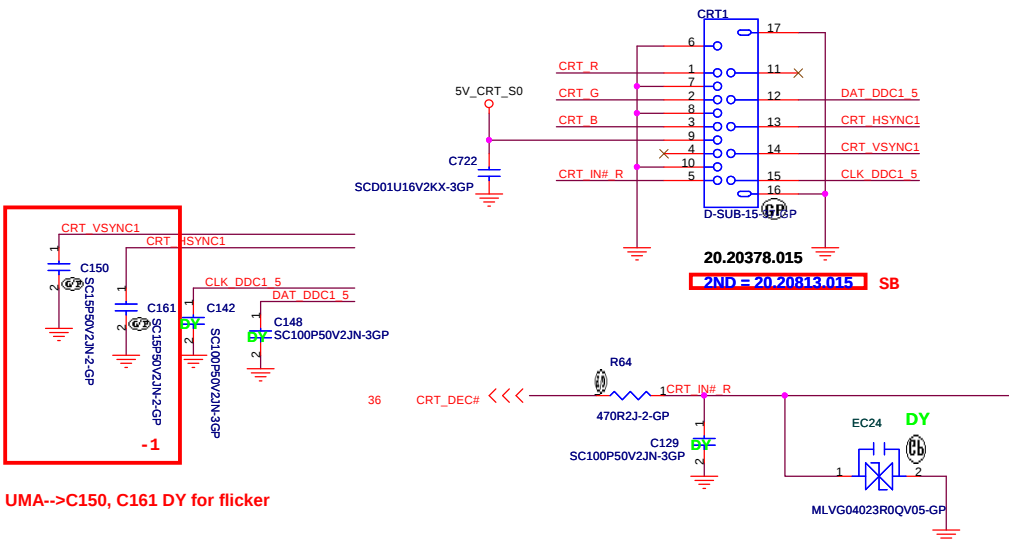
CCD Pin	
Pin	Symbol
1	CCD_PWR
2	USB-
3	USB+
4	GND
5	GND



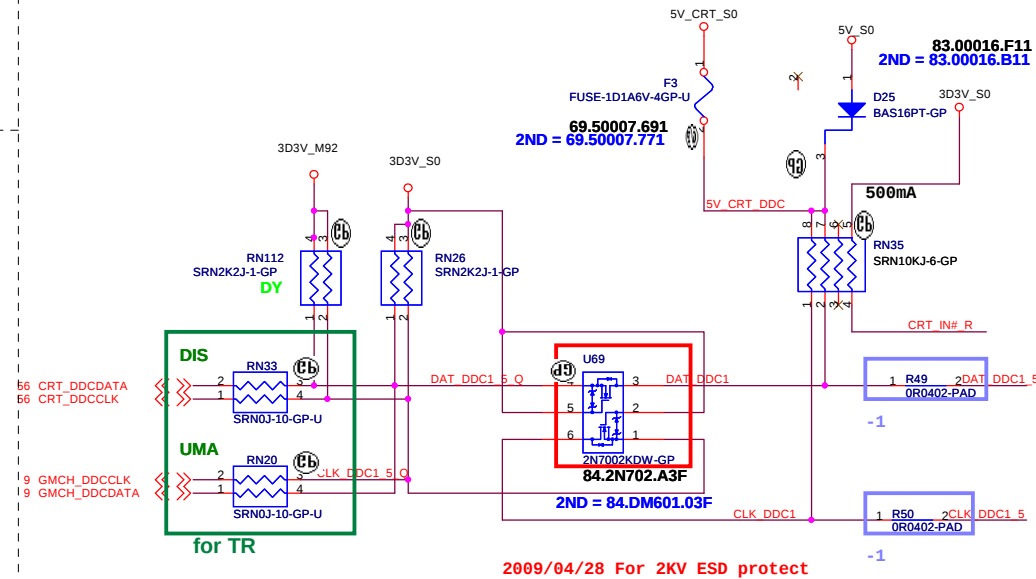
緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.



CRT I/F & CONNECTOR



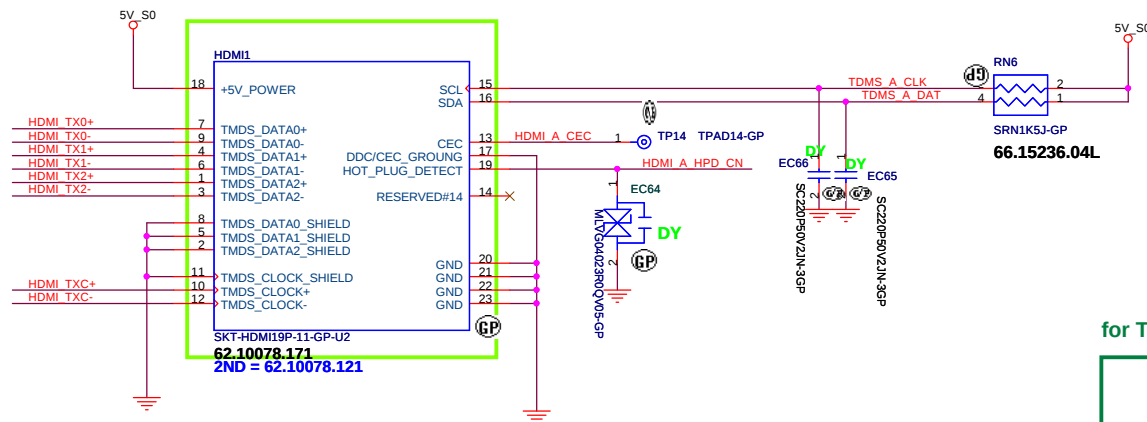
DDC_CLK & DATA level shift



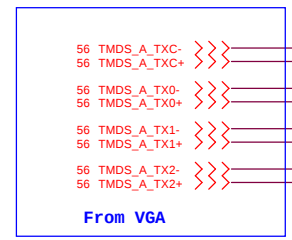
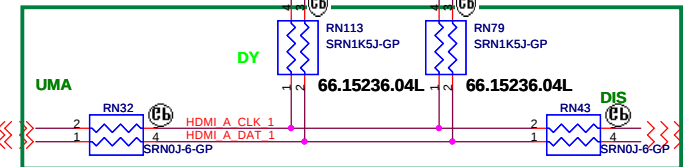
JV50-TR8

緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

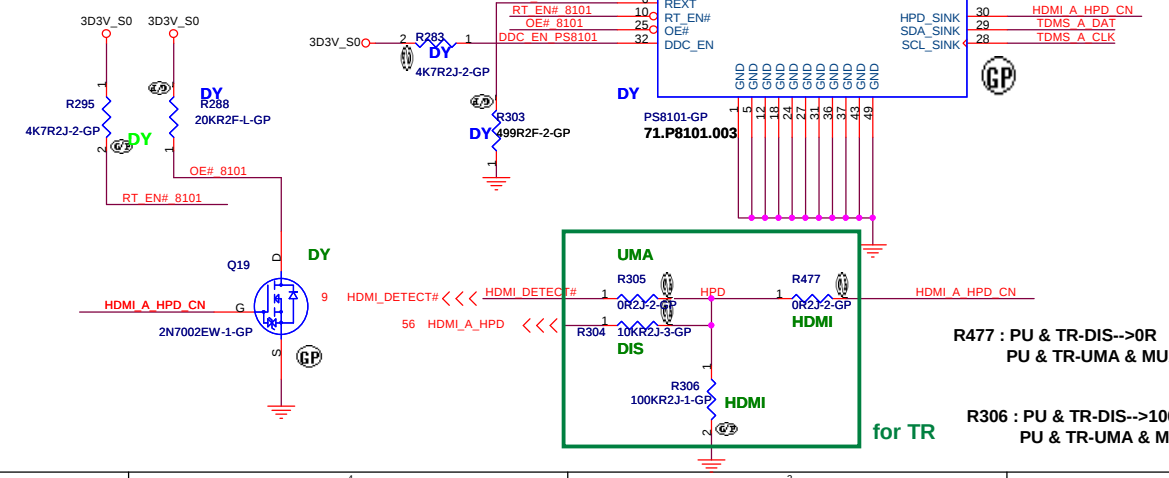
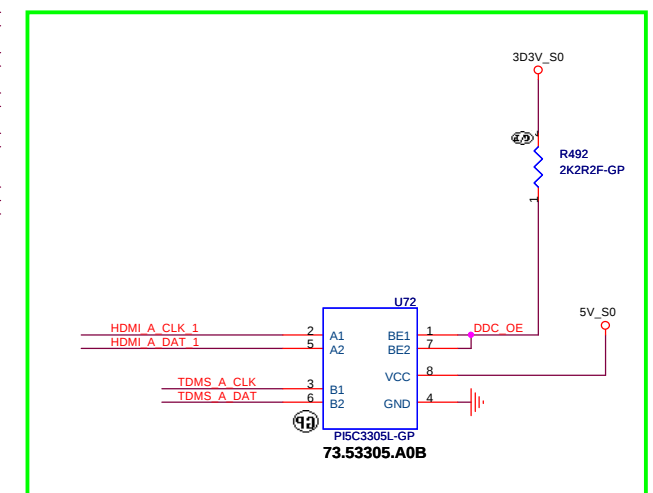
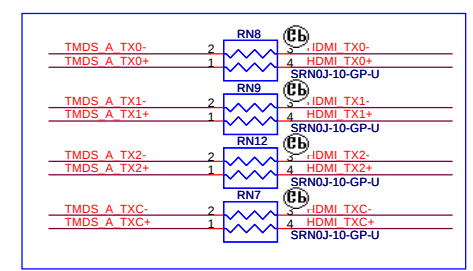
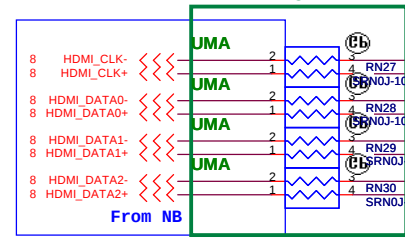
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CRT Connector		
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for TR



for TR

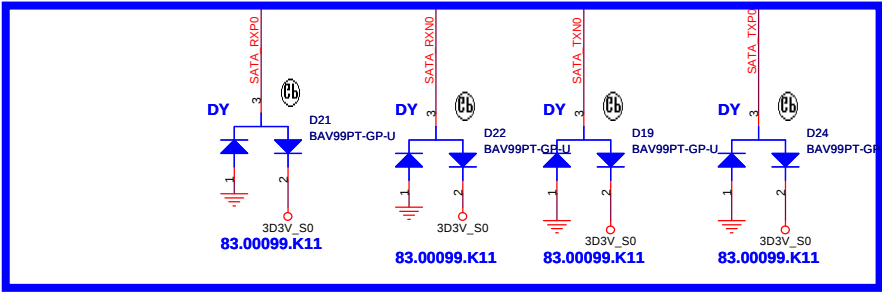
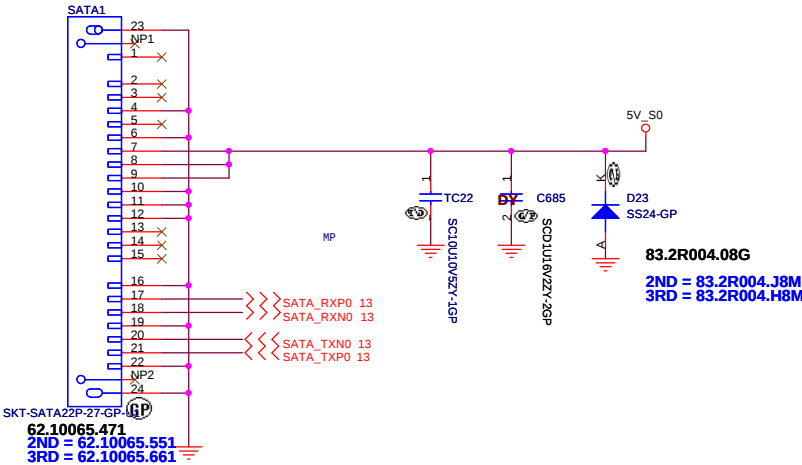


R477 : PU & TR-DIS-->0R
PU & TR-UMA & MUXLESS-->5.1K

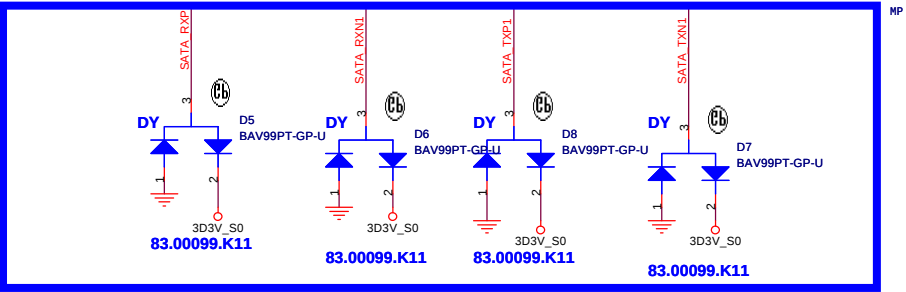
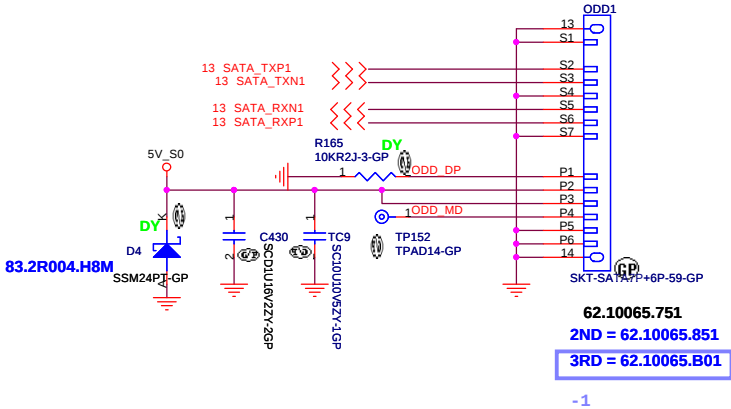
R306 : PU & TR-DIS-->100K
PU & TR-UMA & MUXLESS-->10K

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
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HDMI Connector			
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SATA Connector

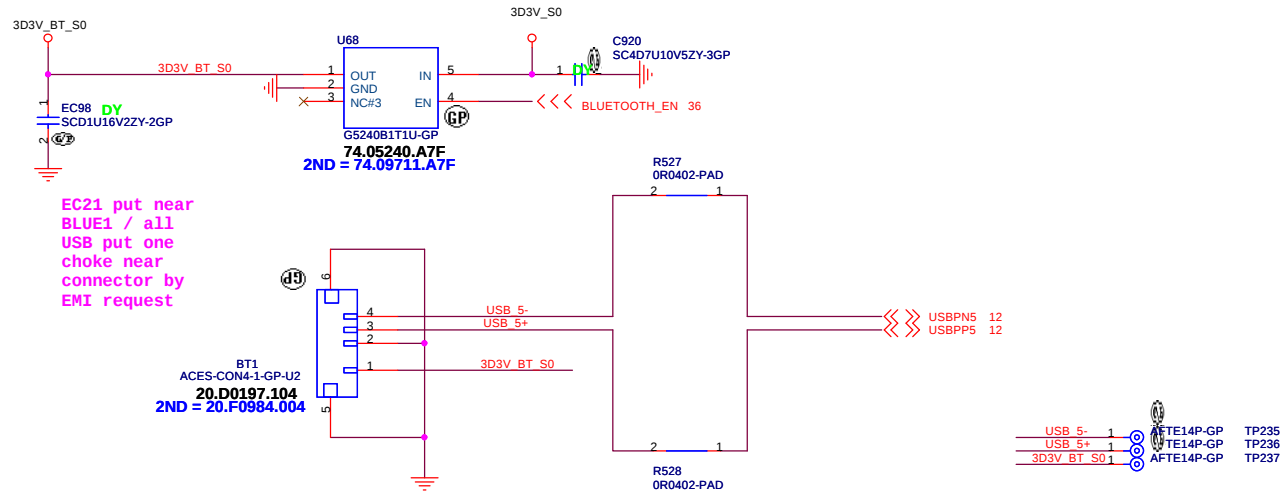


SATA ODD Connector



BLUETOOTH MODULE

1.5A / High Active Voltage 2V



JV50-TR8

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Title

BLUETOOTH

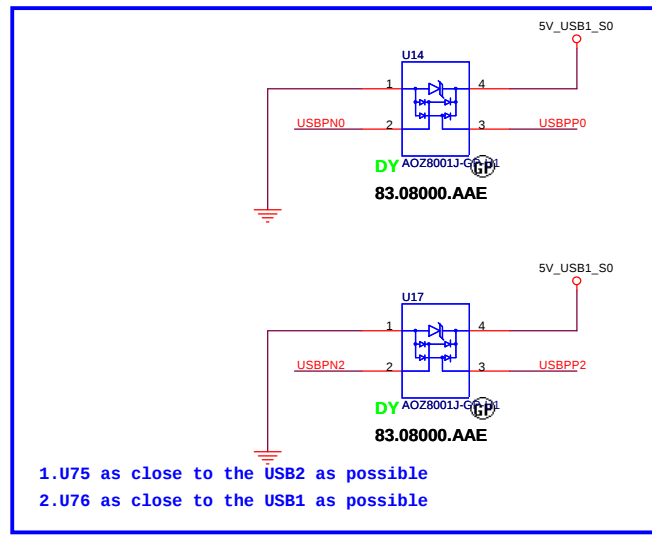
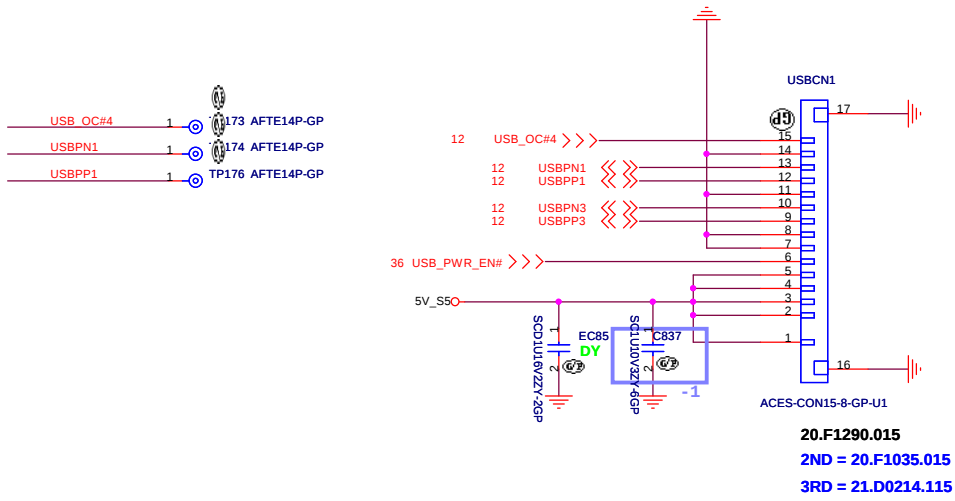
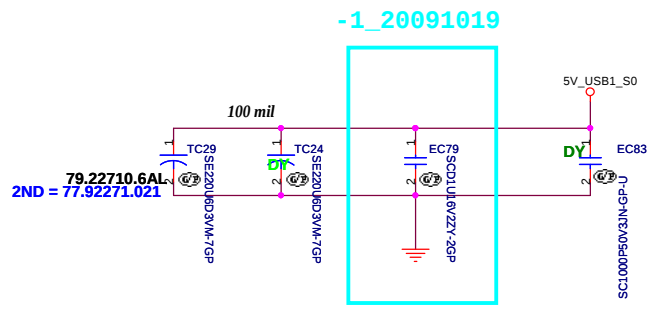
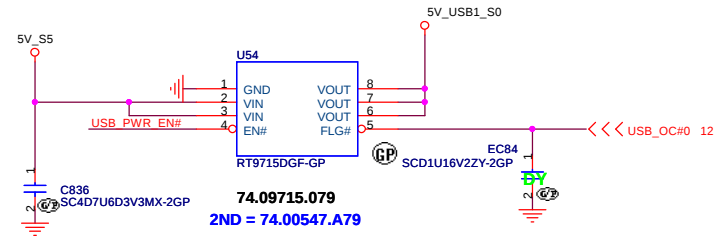
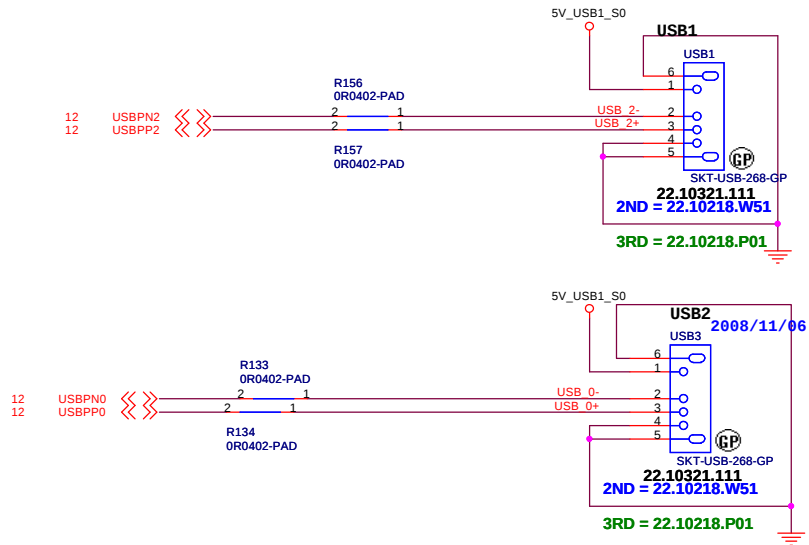
Size

Document Number

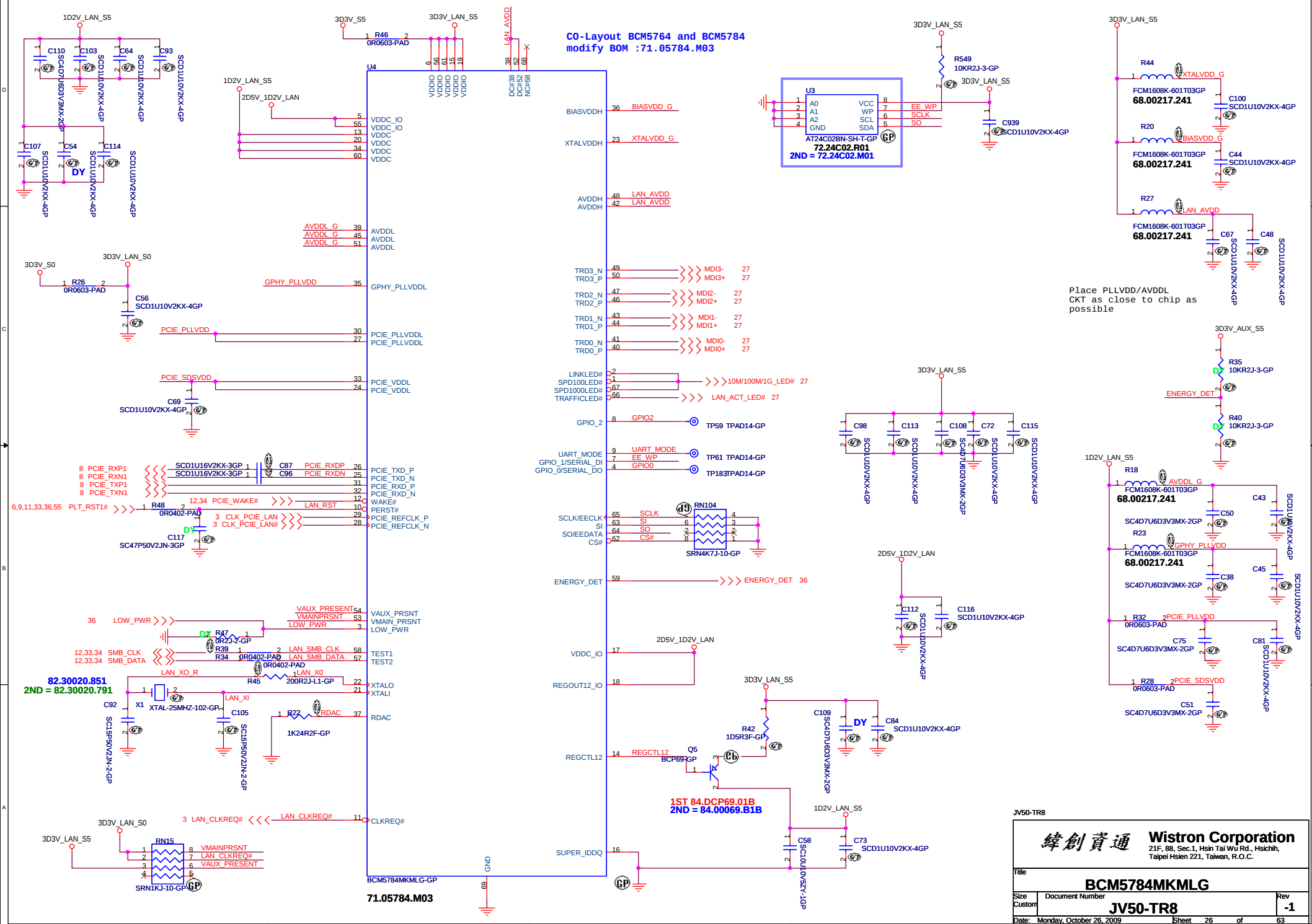
JV50-TR8

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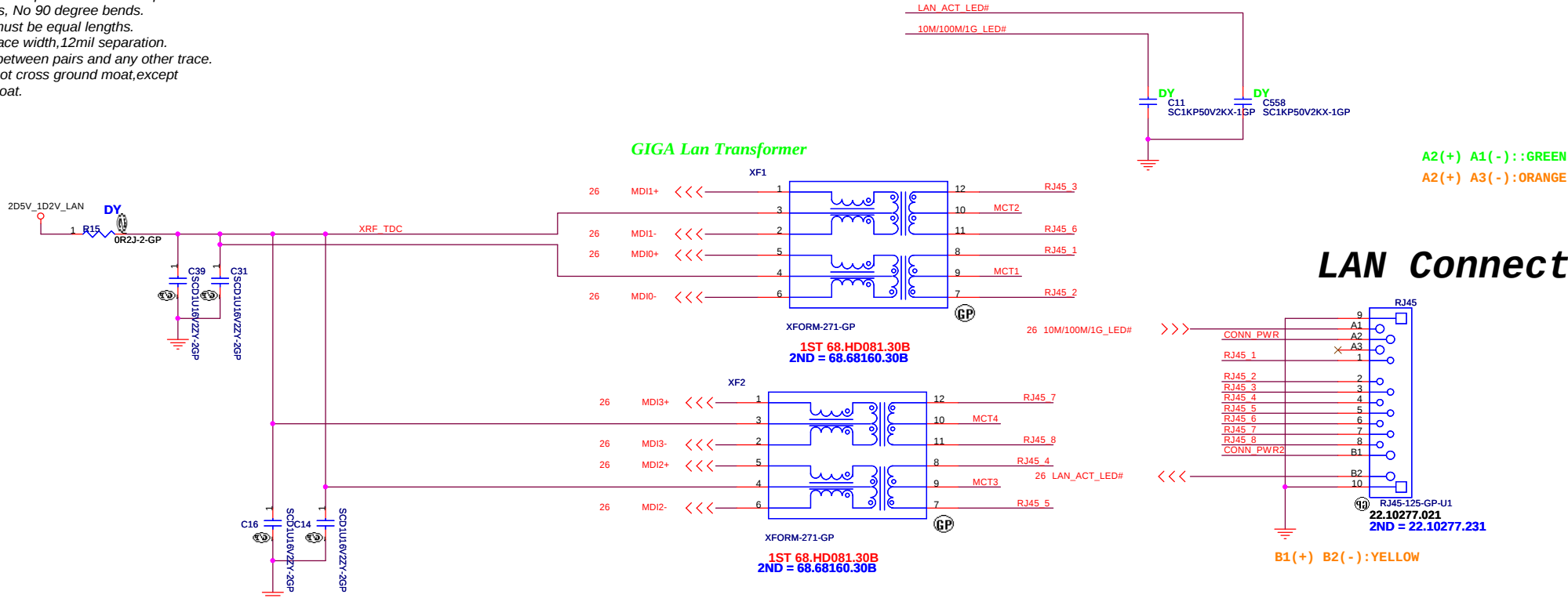


1.U75 as close to the USB2 as possible
 2.U76 as close to the USB1 as possible



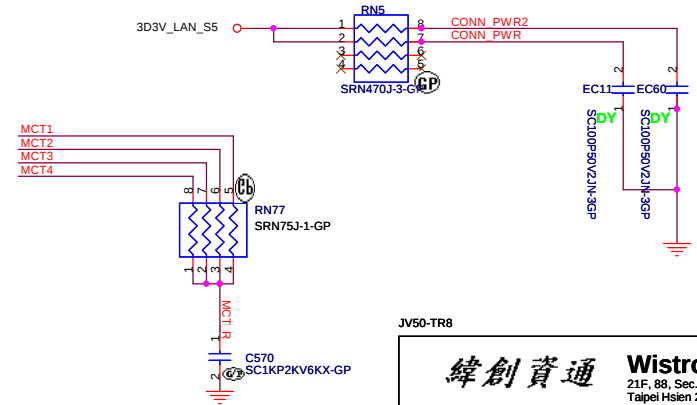
LAN Connector

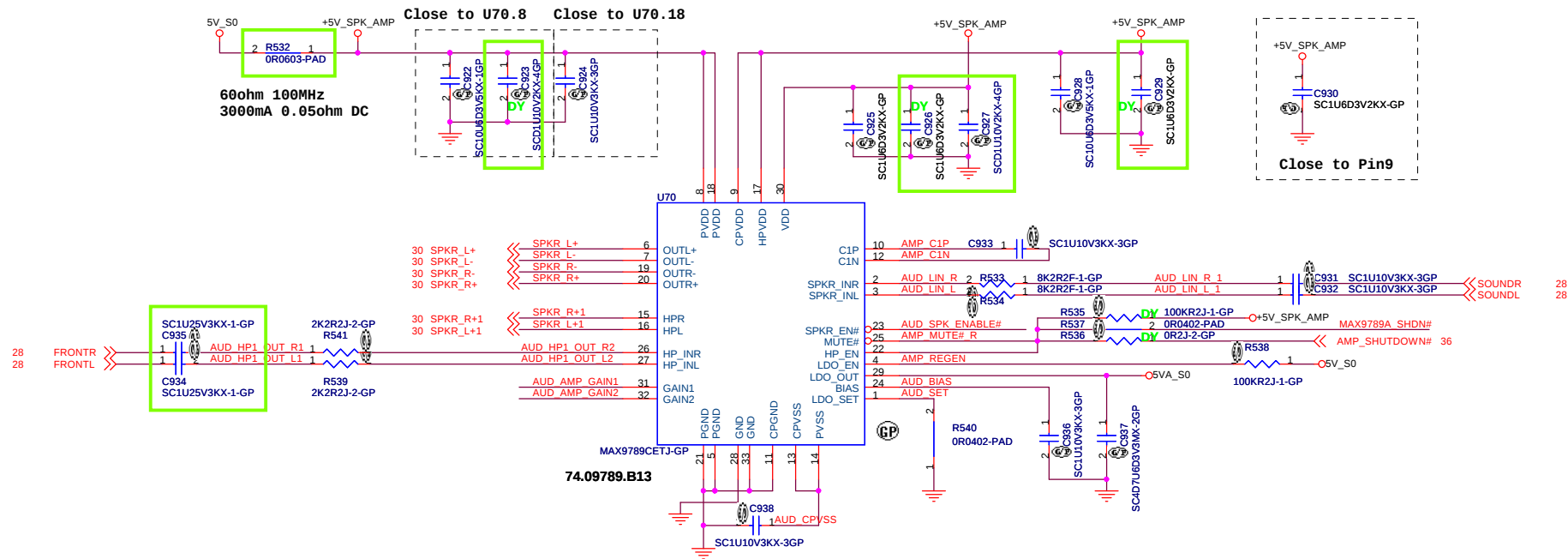
- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.



LAN Connector

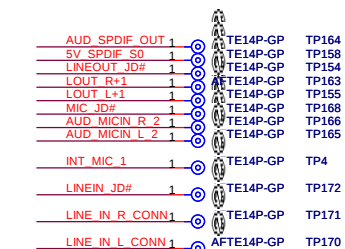
DOC_TIP,DOC_RING,TIP,RING:
W/S : 10/100 @ Surface layers
10/20 @ Inner layers





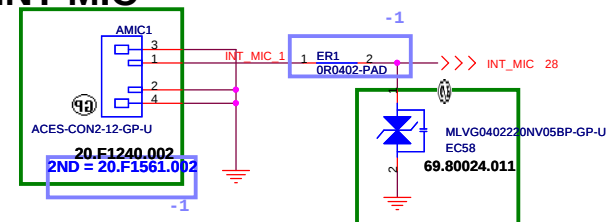
JV50-TR8

29	SPKR_L-	SPKR_L-
29	SPKR_L+	SPKR_L+
29	SPKR_R-	SPKR_R-
29	SPKR_R+	SPKR_R+



The schematic shows the G5240B7F audio amplifier (U56) configured as follows:

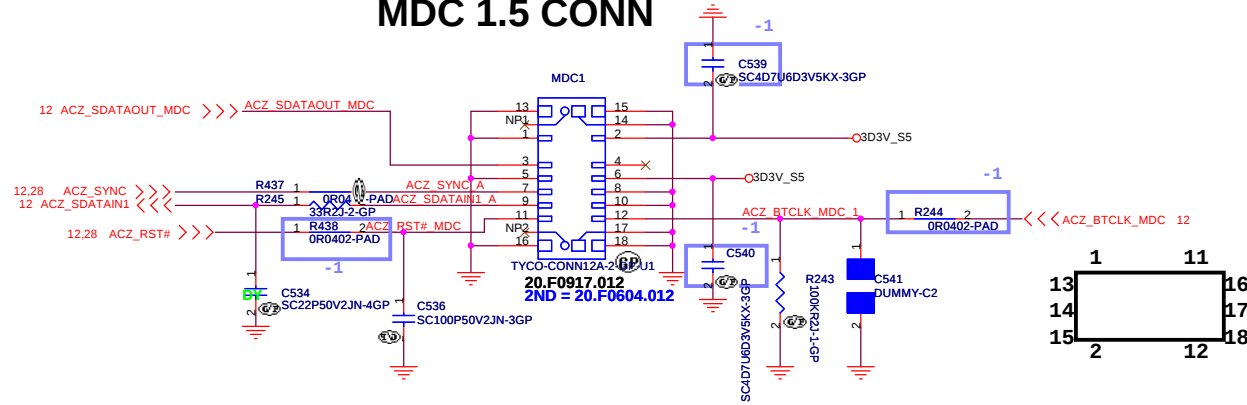
- Power Supply:** The VDD pin is connected to a 5V supply labeled "5V_SPDIF S0". The GND pin is connected to ground.
- Input Stage:** The IN pin is connected to the output of a CD player (CDP), which is also labeled "LINEOUT JD#". A capacitor C851 (SCD1U16V2ZY-2GP) is connected between the input signal line and ground.
- Output Stage:** The OUT pin is connected to the positive terminal of a speaker or earphone, which is also labeled "DX". A resistor R472 is connected between the output and ground. A capacitor C853 (SCD1U16V2ZY-2GP) is connected between the output and ground.



緯創資通

Title			
AUDIO JACK			
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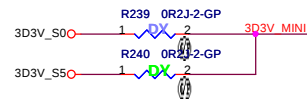
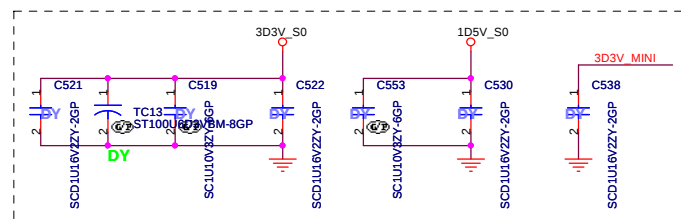
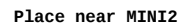
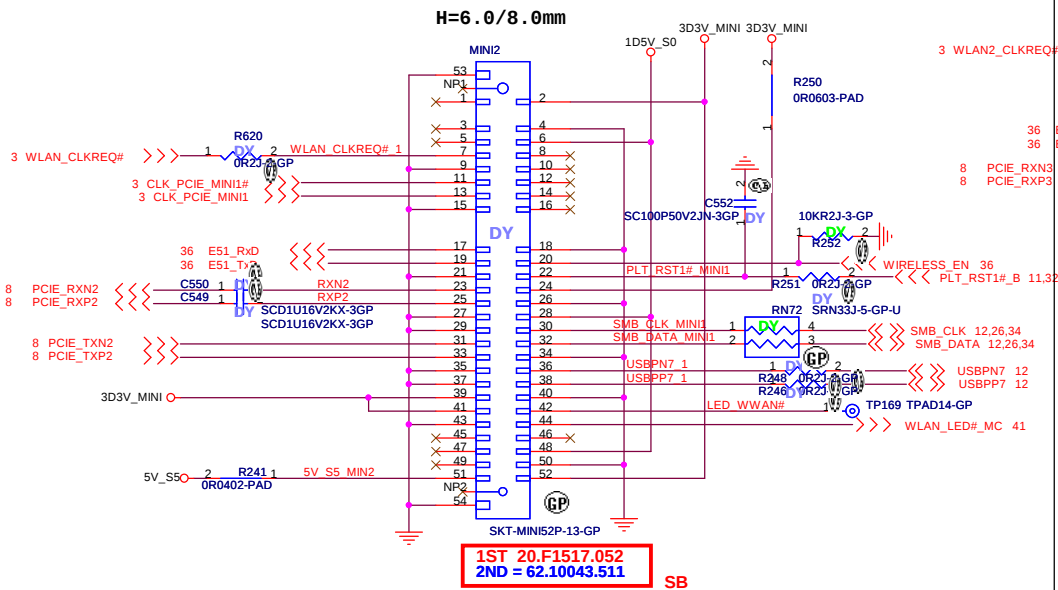
MDC 1.5 CONN



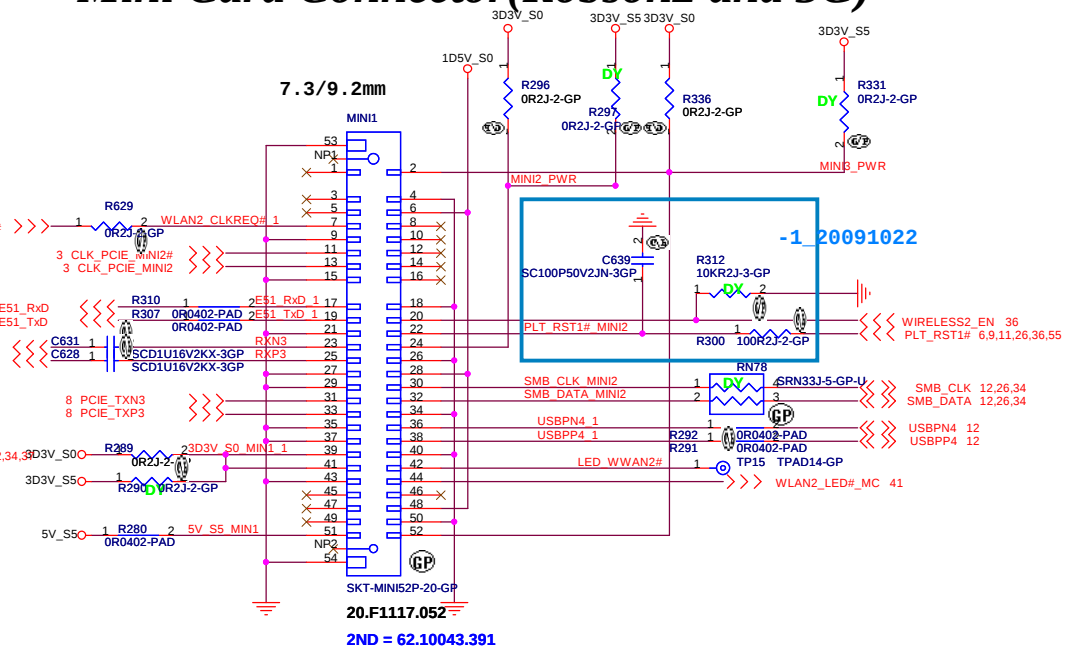
JV50-TR8

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Title			
MDC			
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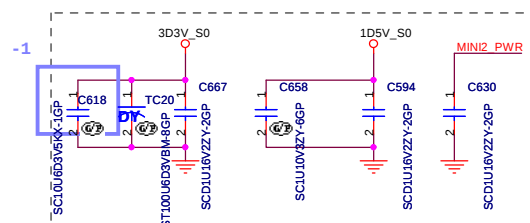
Mini Card Connector(WLAN)



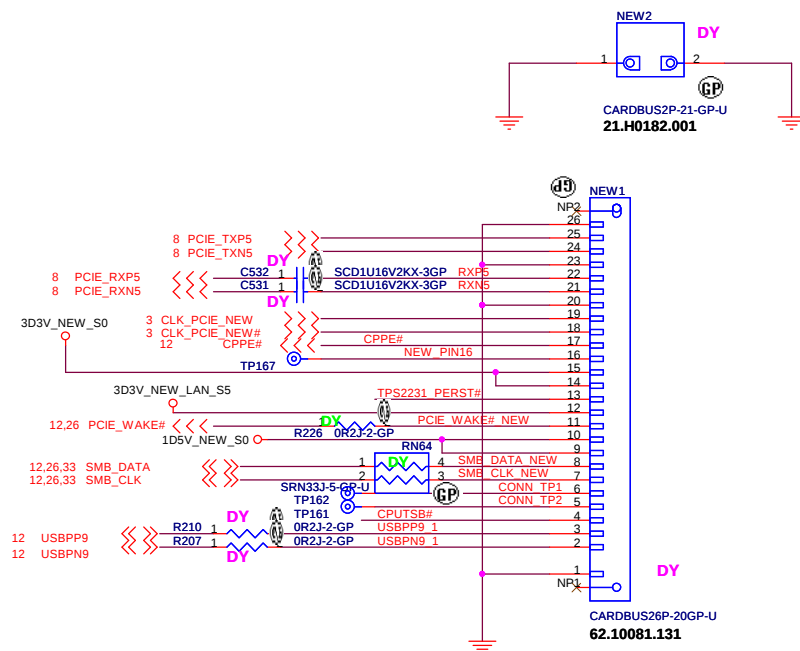
Mini Card Connector(Robson2 and 3G)



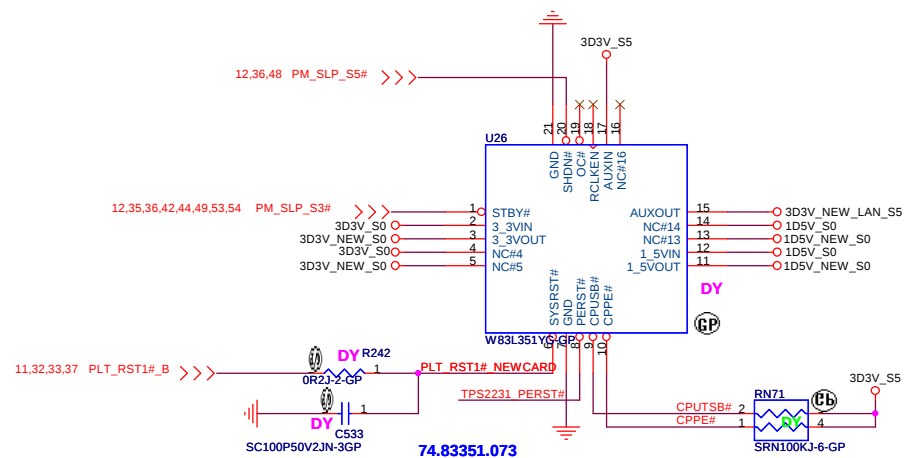
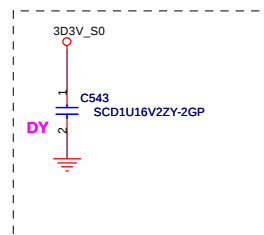
Place near MINI1



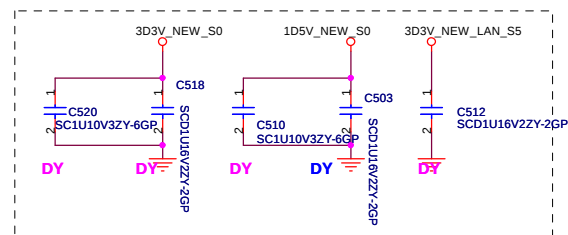
NEWCARD Connector



Place them Near to Chip



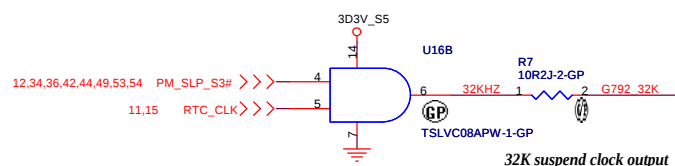
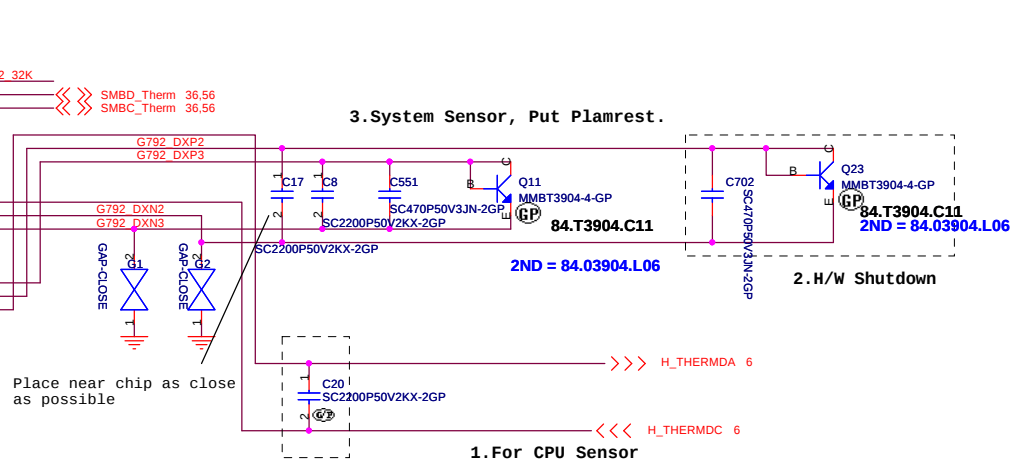
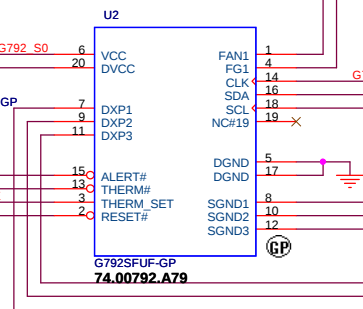
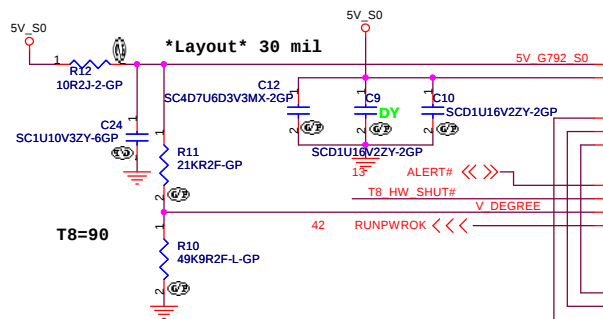
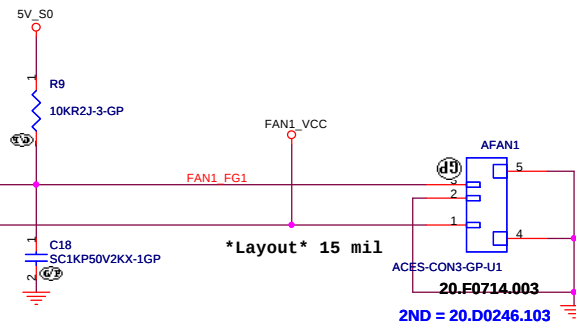
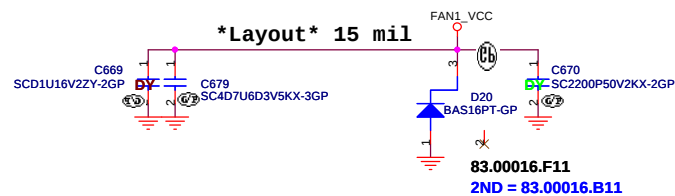
Place them Near to Connector



JV50-TR8

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Title			
NEW CARD			
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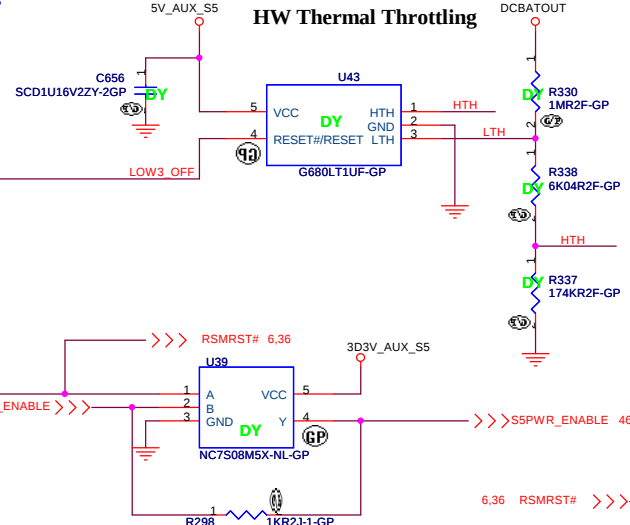


DXP1:108 Degree
DXP2:H/W Setting
DXP3:88 Degree

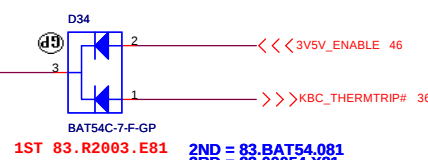
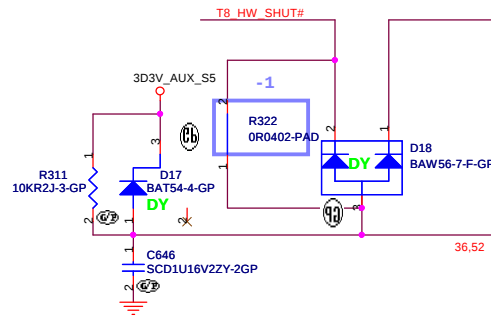
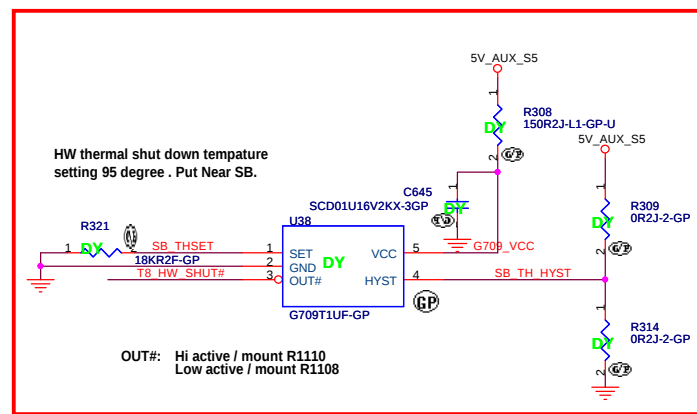
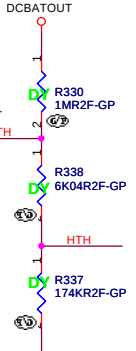
Place near chip as close as possible

73.07408.L16
2ND = 73.07408.L15
3RD = 73.07408.02B

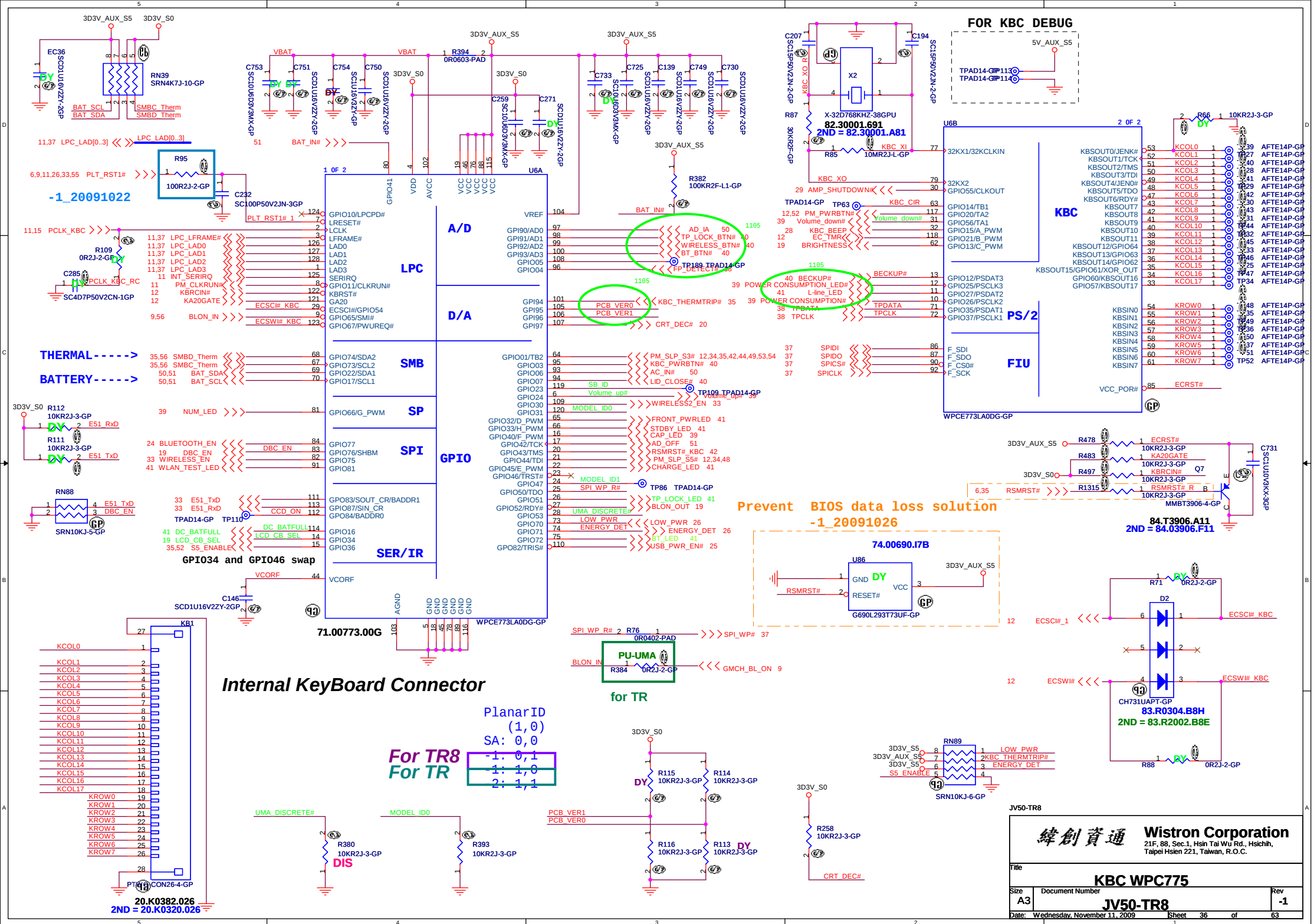
HW Thermal Throttling

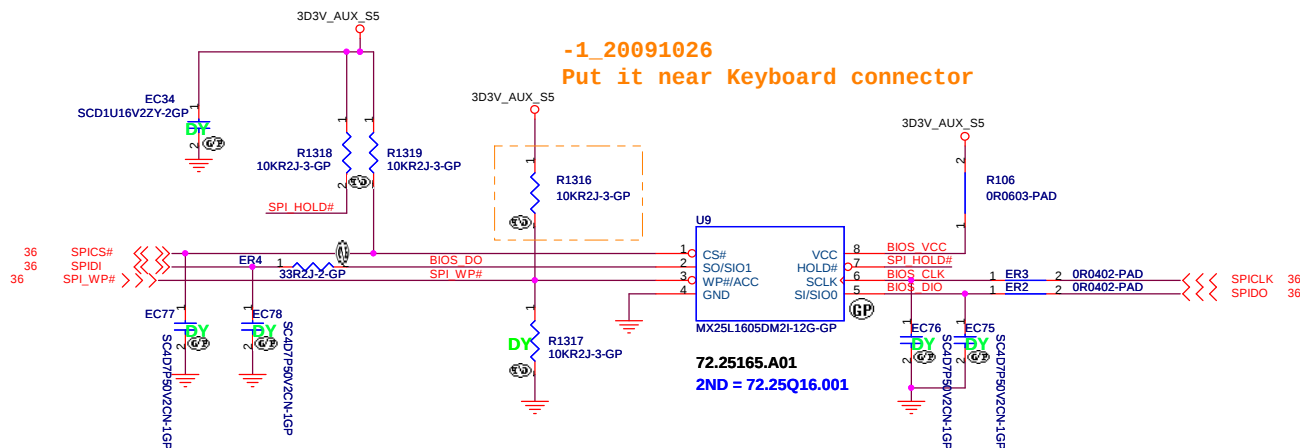


BL3#

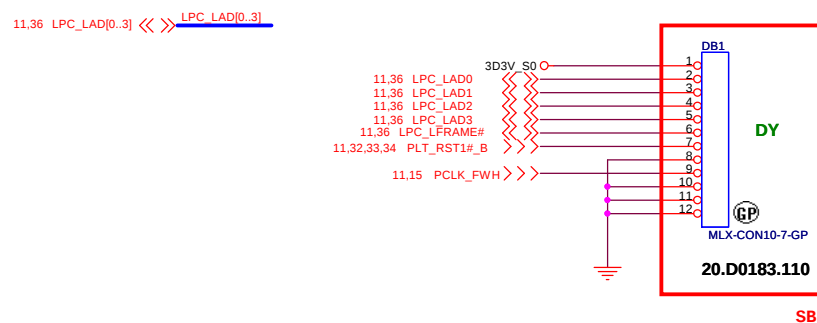


JV50-TR8





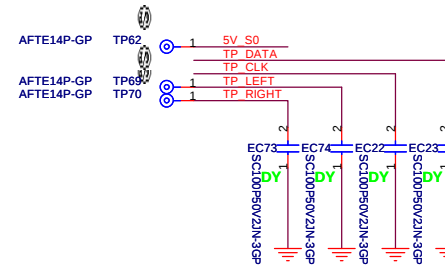
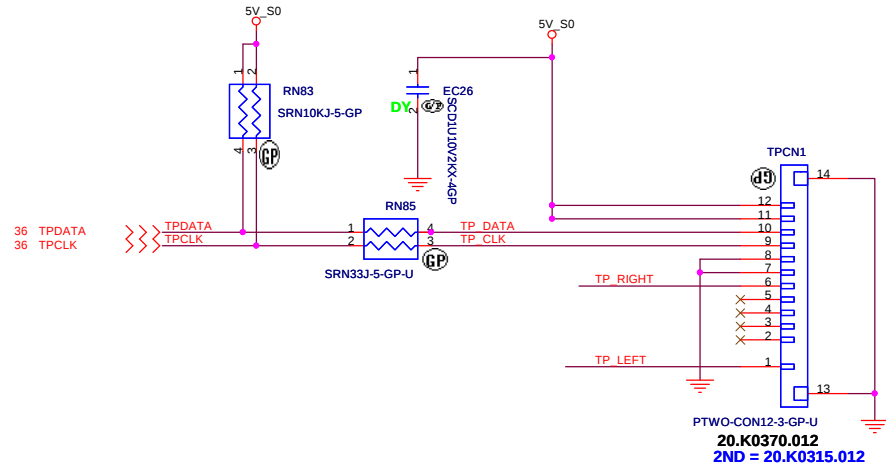
16M Bits
SPI FLASH ROM
GOLDEN FINGER FOR DEBUG BOARD



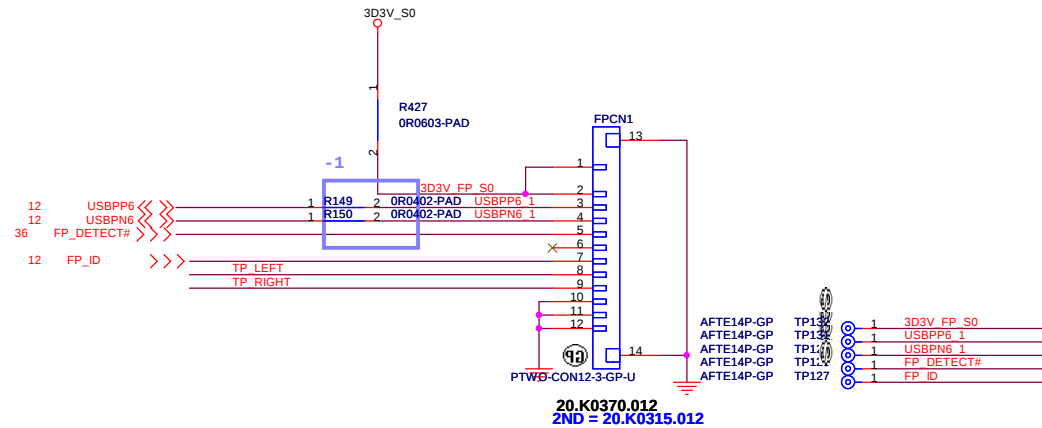
JV50-TR8

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
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TOUCH PAD



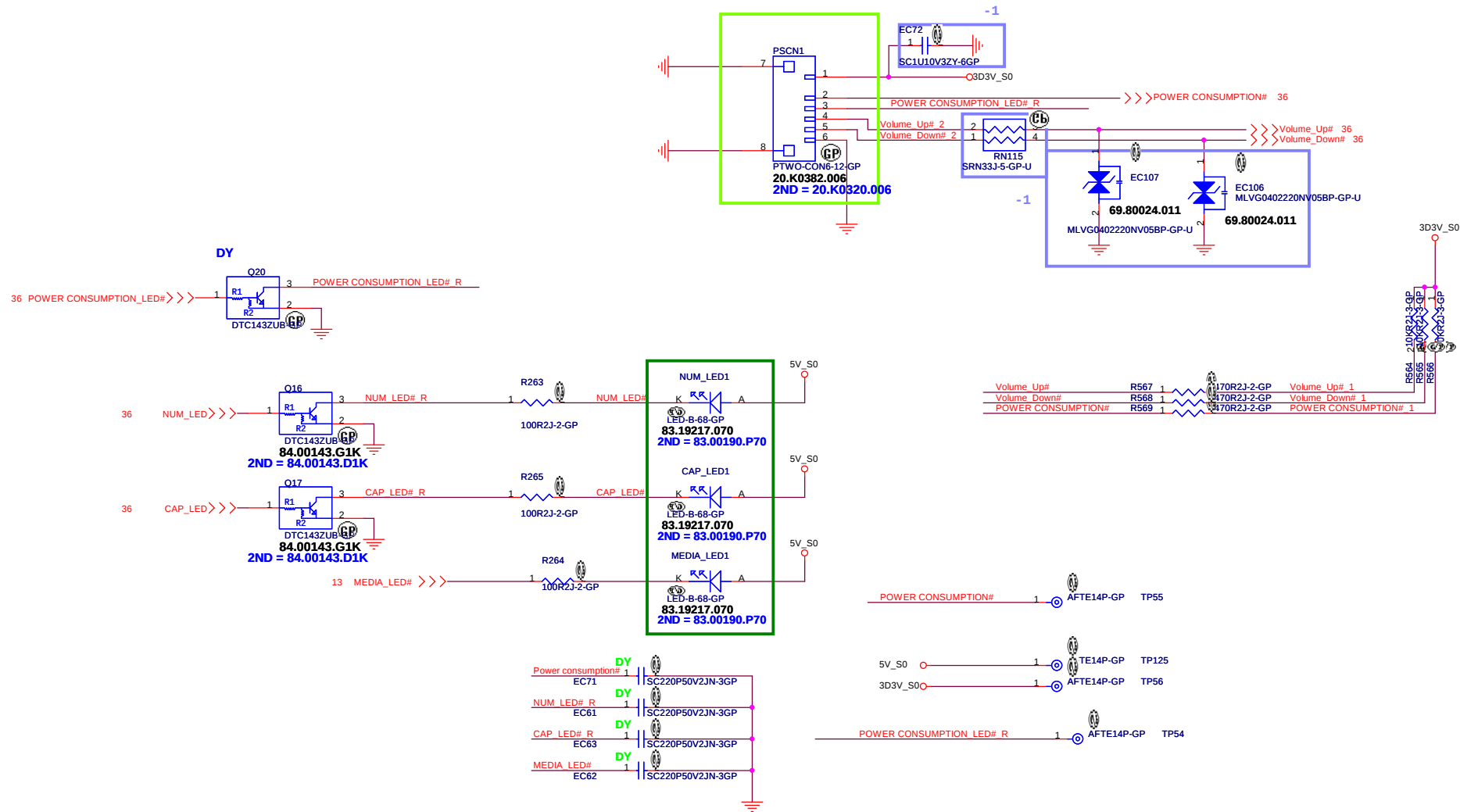
Finger printer



JV50-TR8

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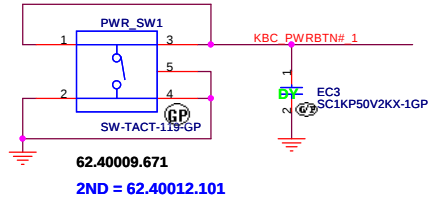
Title		
Touch PAD/Finger printer		
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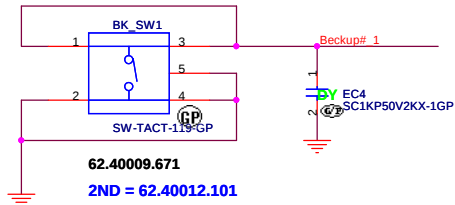
緯創資通 Wistron Corporation
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Title		
LAUNCH BOARD		
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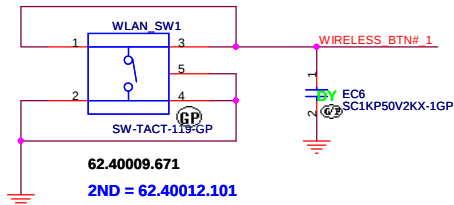
Power Button



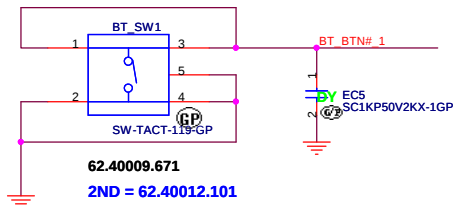
Beckup Button



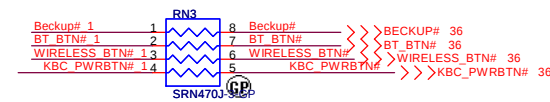
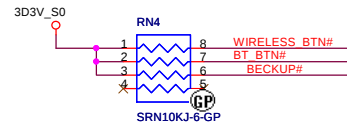
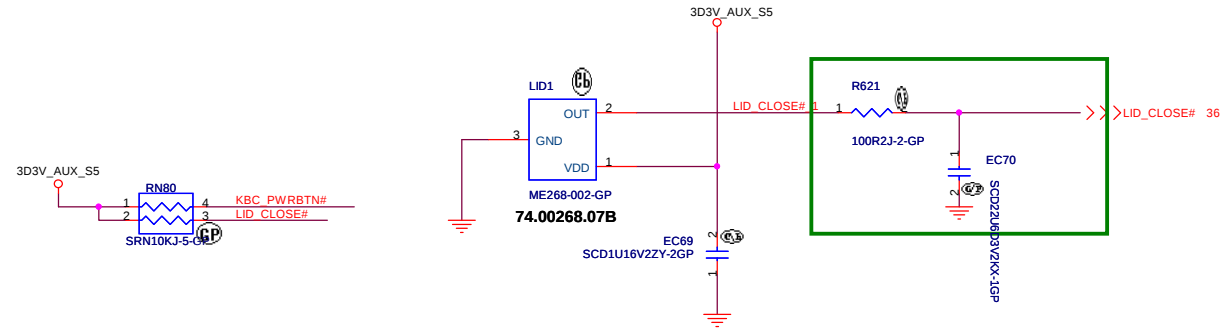
WIRELESS Button



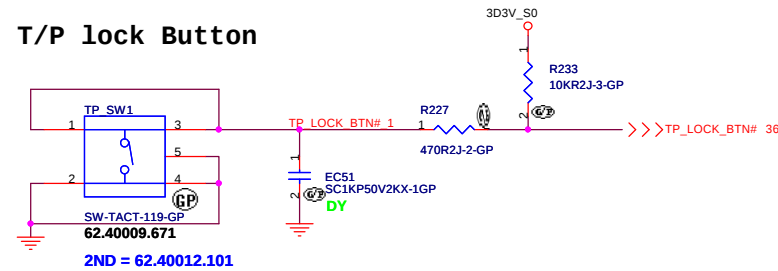
BT/3G Button



Cover Up Switch



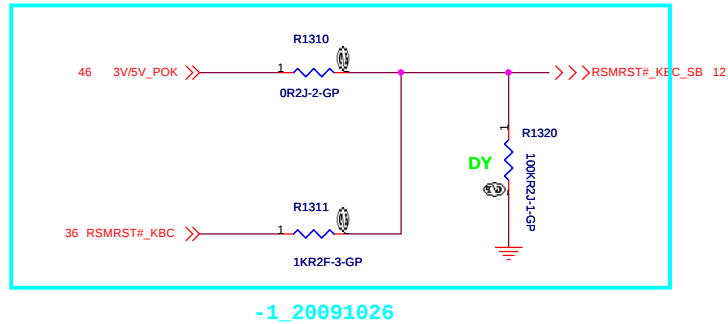
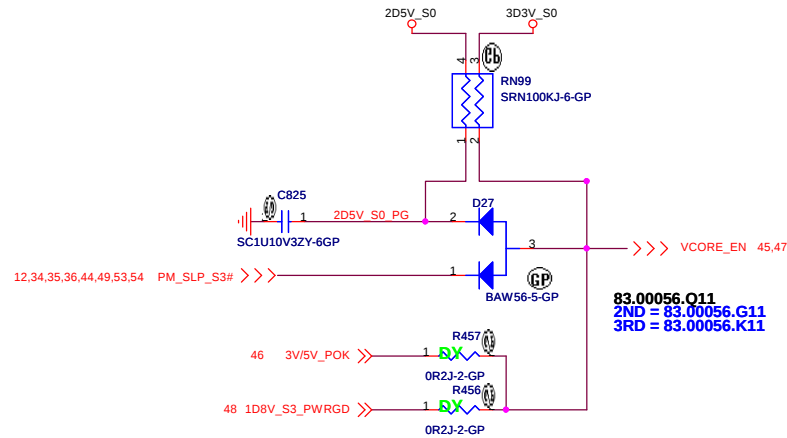
T/P lock Button



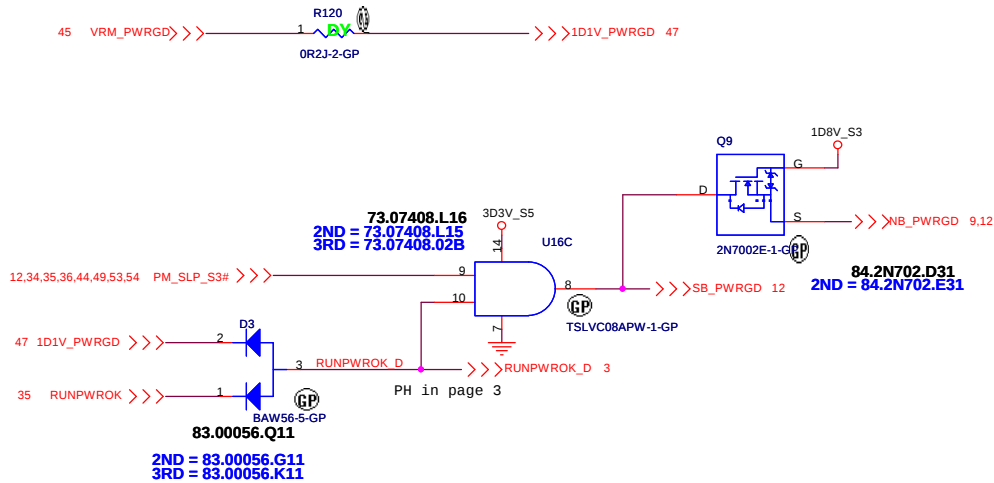
緯創資通

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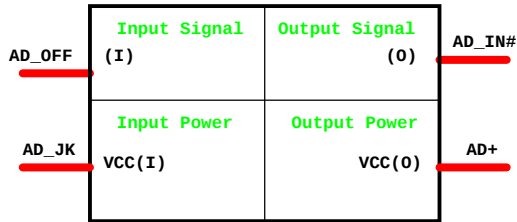
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SWITCH		
Size	Document Number	Rev
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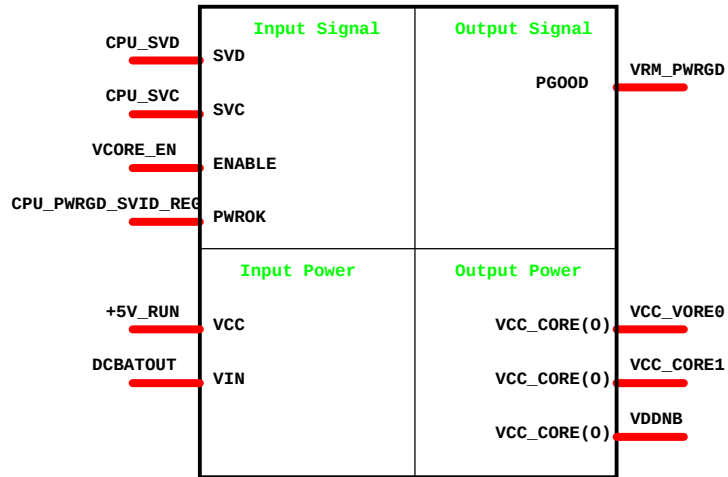
P/H @ 1D8V_S3 PAGE



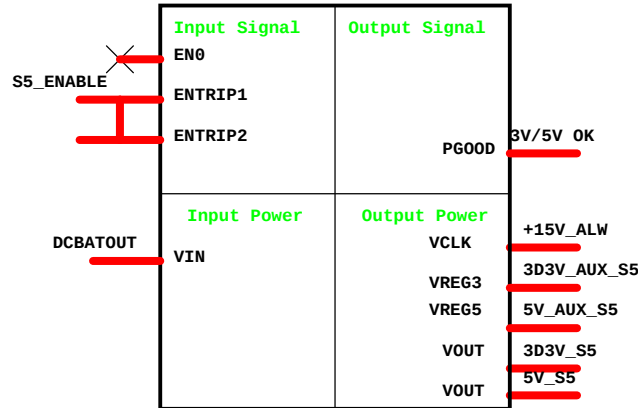
Adapter



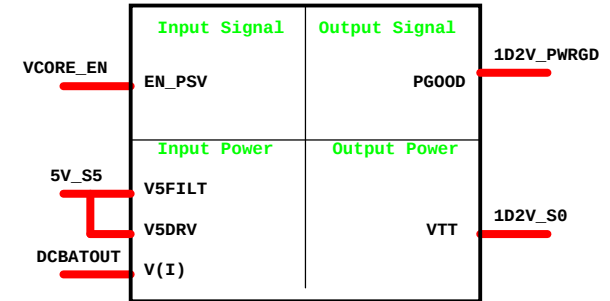
CPU_CORE ISL6265HRTZ



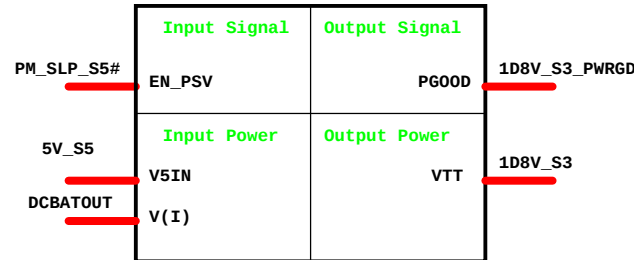
DCDC 5V/3D3V(RT8205A)



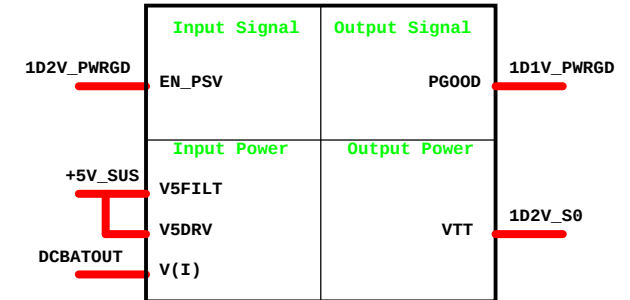
DCDC 1D2V(TPS51124)



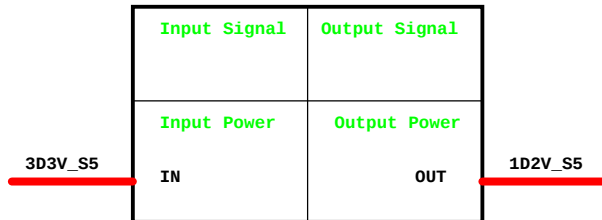
DCDC 1D8V(RT8209B)



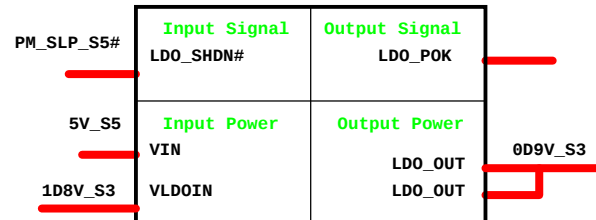
DCDC 1D1V(TPS51124)



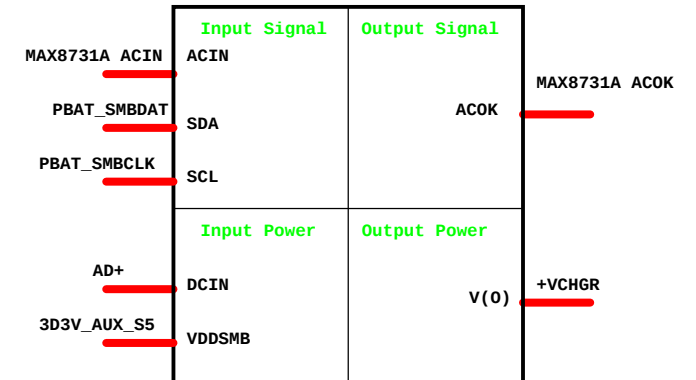
1D2V LDO G9161



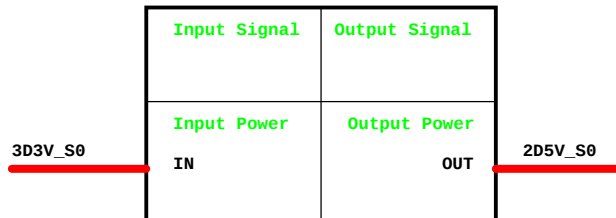
0D9V LDO RT9026



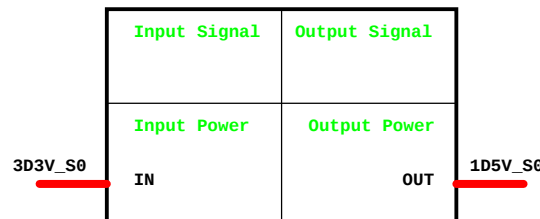
CHARGER MAX8731



2D5V LDO R9161

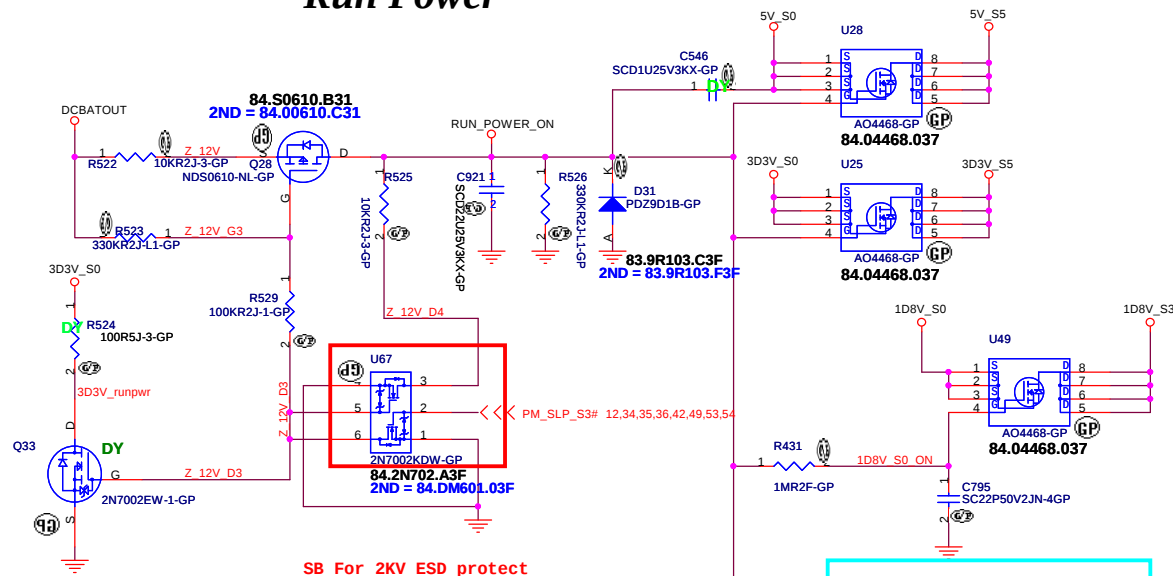


1D5V LDO G9571

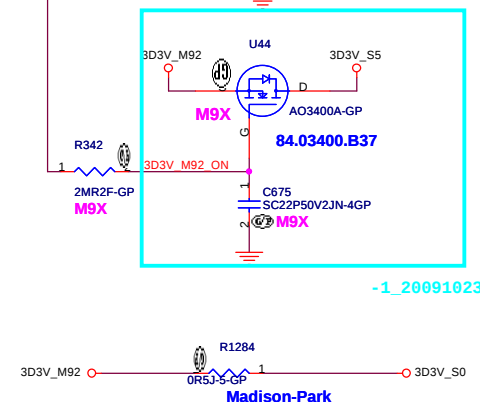
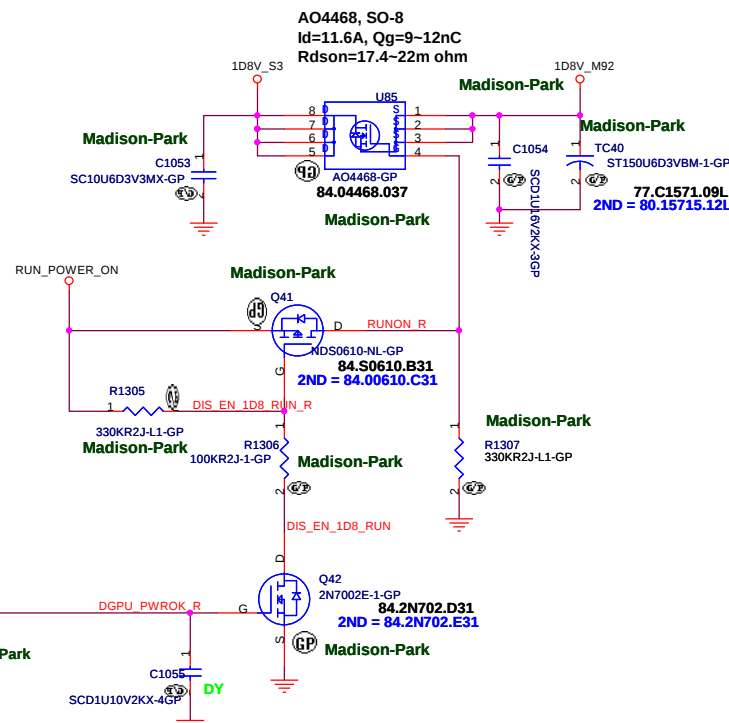


JV50-TR8

Run Power



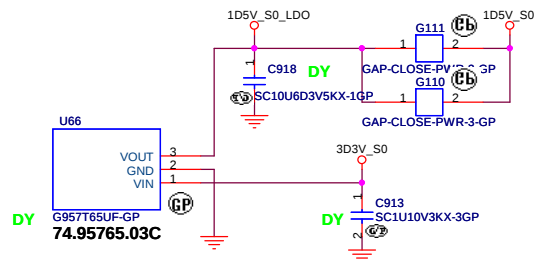
for TR





G957

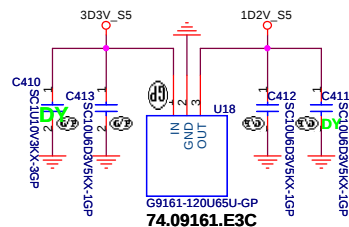
1D5V_S0
Iomax=1A



For MINI Card.NEW Card power SW

G9161

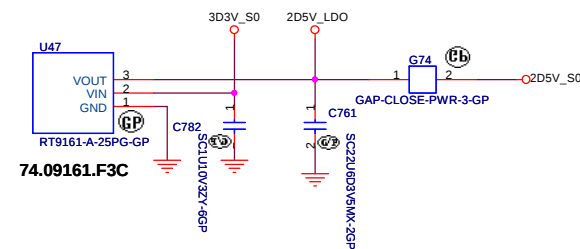
1D2V_S5
Iomax=400mA



Place near to SB710

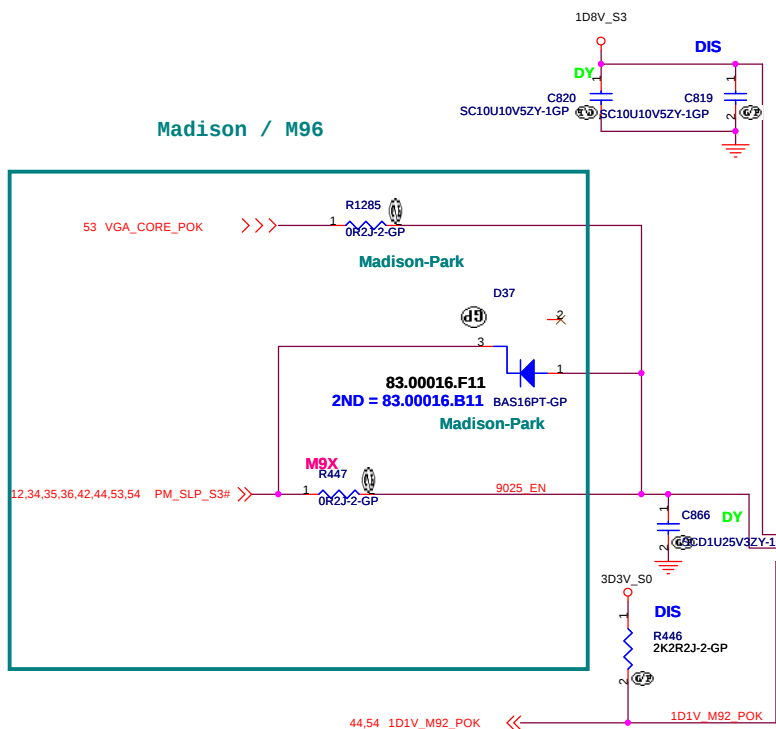
RT9161A

2D5V
Iomax=0.2A



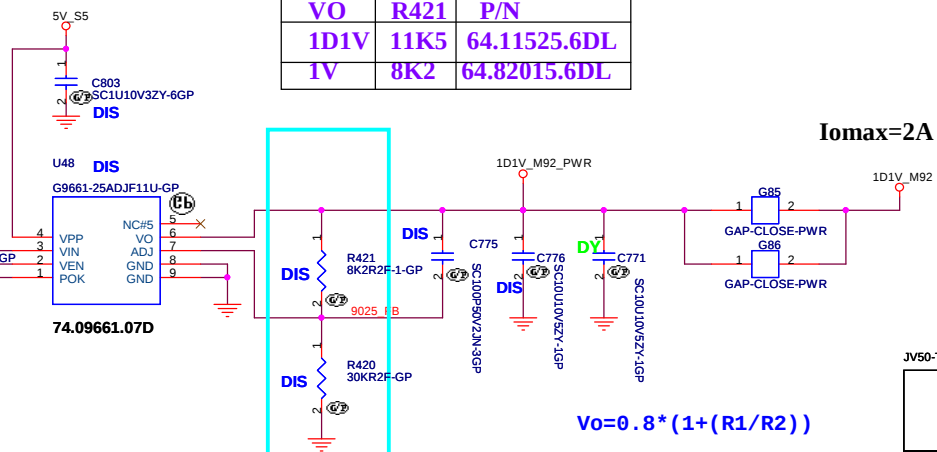
Place near to CPU

Madison / M96



Now set to 1V for Madison

VO	R421	P/N
1D1V	11K5	64.11525.6DL
1V	8K2	64.82015.6DL

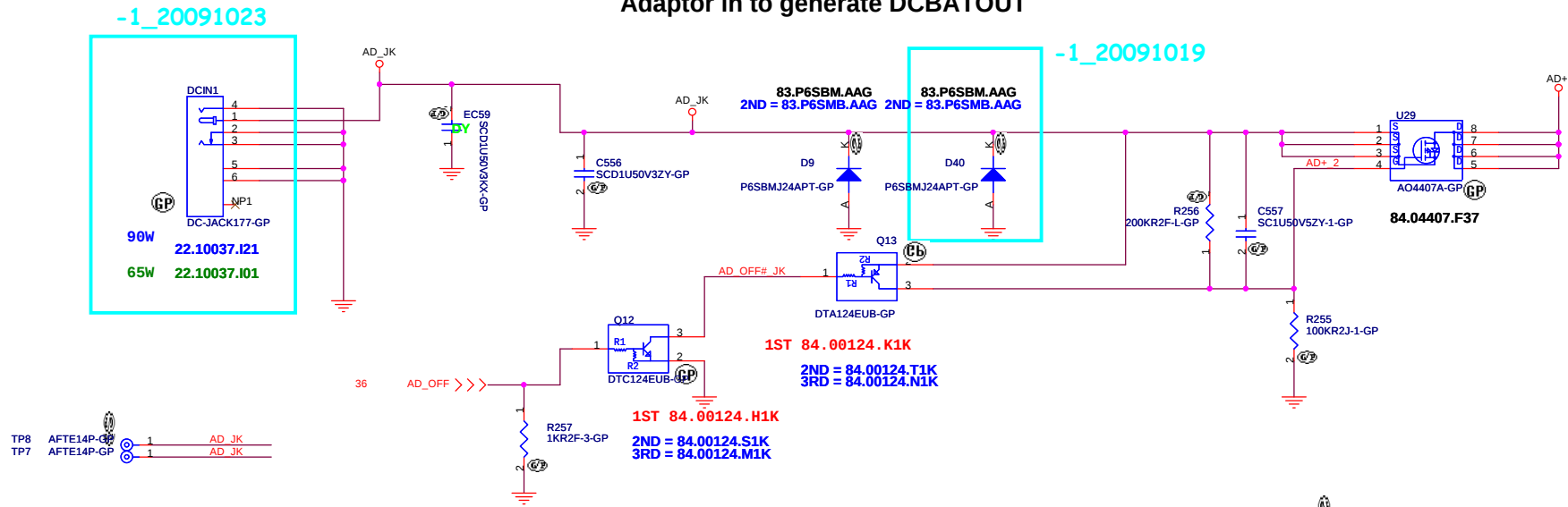


$$Vo = 0.8 * (1 + (R1/R2))$$

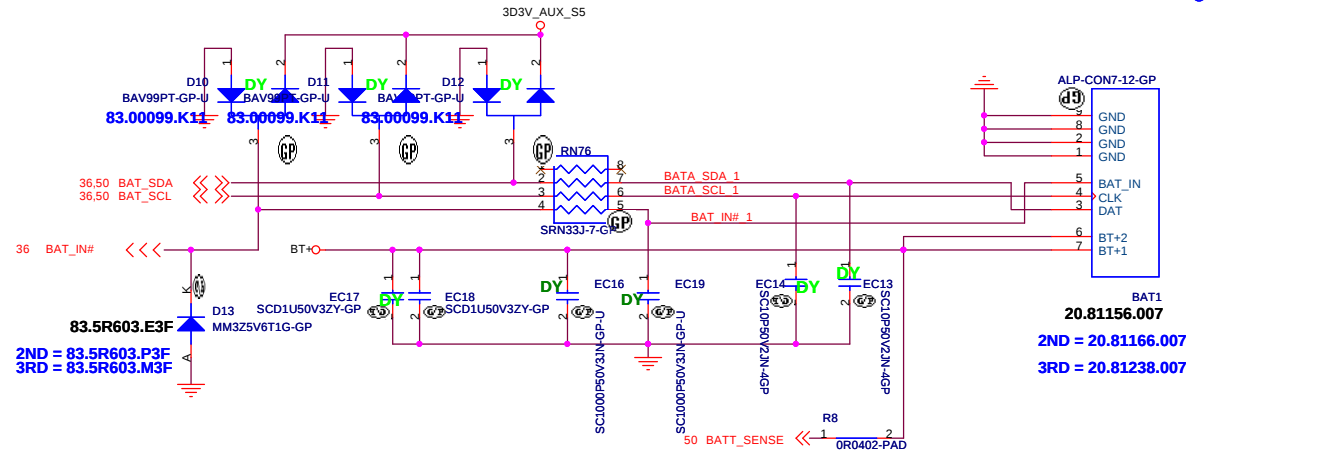
-1_20091019

JV50-TR8

Adaptor in to generate DCBATOUT



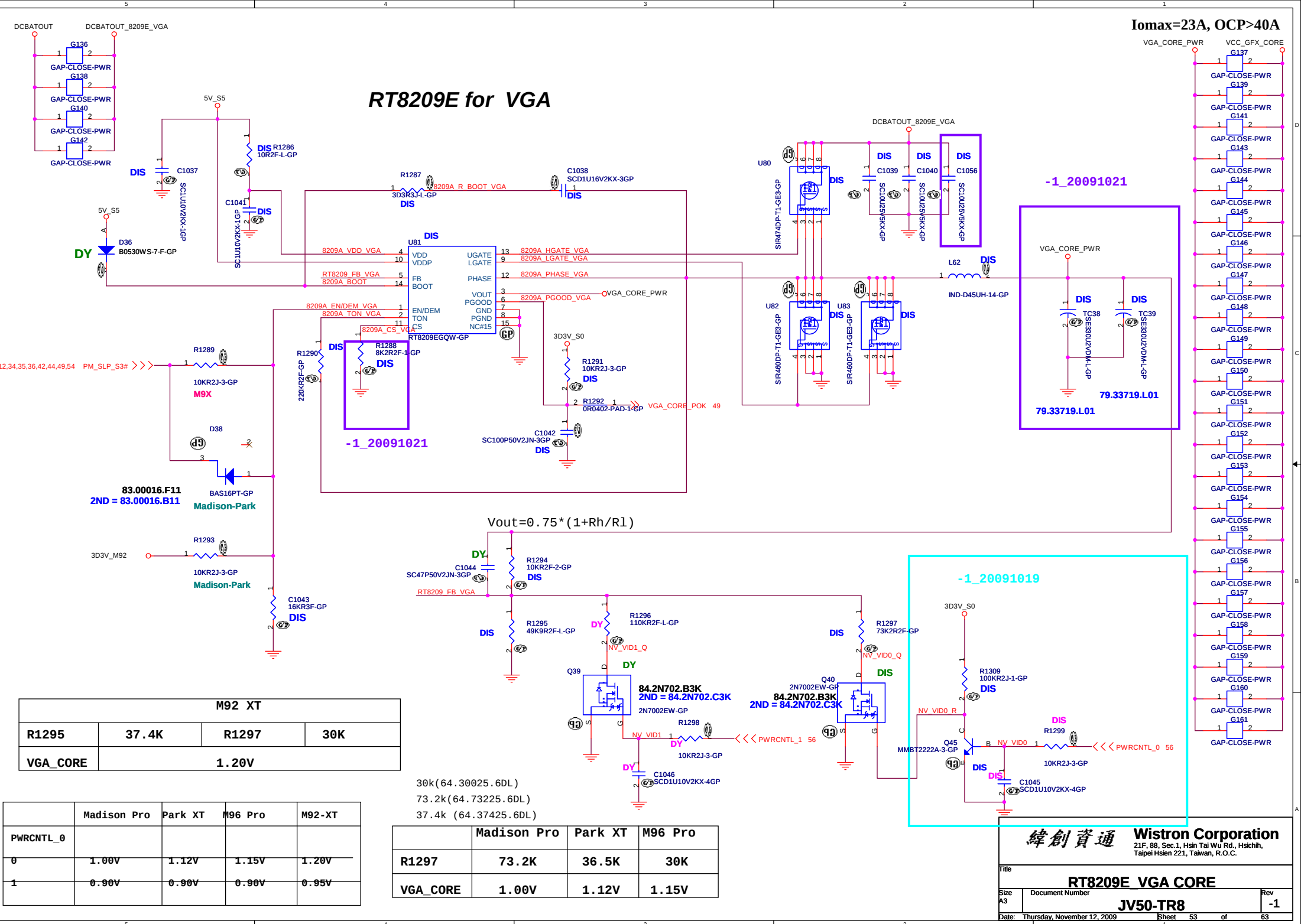
BATTERY CONNECTOR



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RT8209E for VGA

Iomax=23A, OCP>40A

M92 XT			
R1295	37.4K	R1297	30K
VGA_CORE	1.20V		

	Madison Pro	Park XT	M96 Pro	M92-XT
PWRCNTL_0				
0	1.00V	1.12V	1.15V	1.20V
1	0.90V	0.90V	0.90V	0.95V

	Madison Pro	Park XT	M96 Pro
R1297	73.2K	36.5K	30K
VGA_CORE	1.00V	1.12V	1.15V

緯創資通

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Title

RT8209E VGA CORE

Size

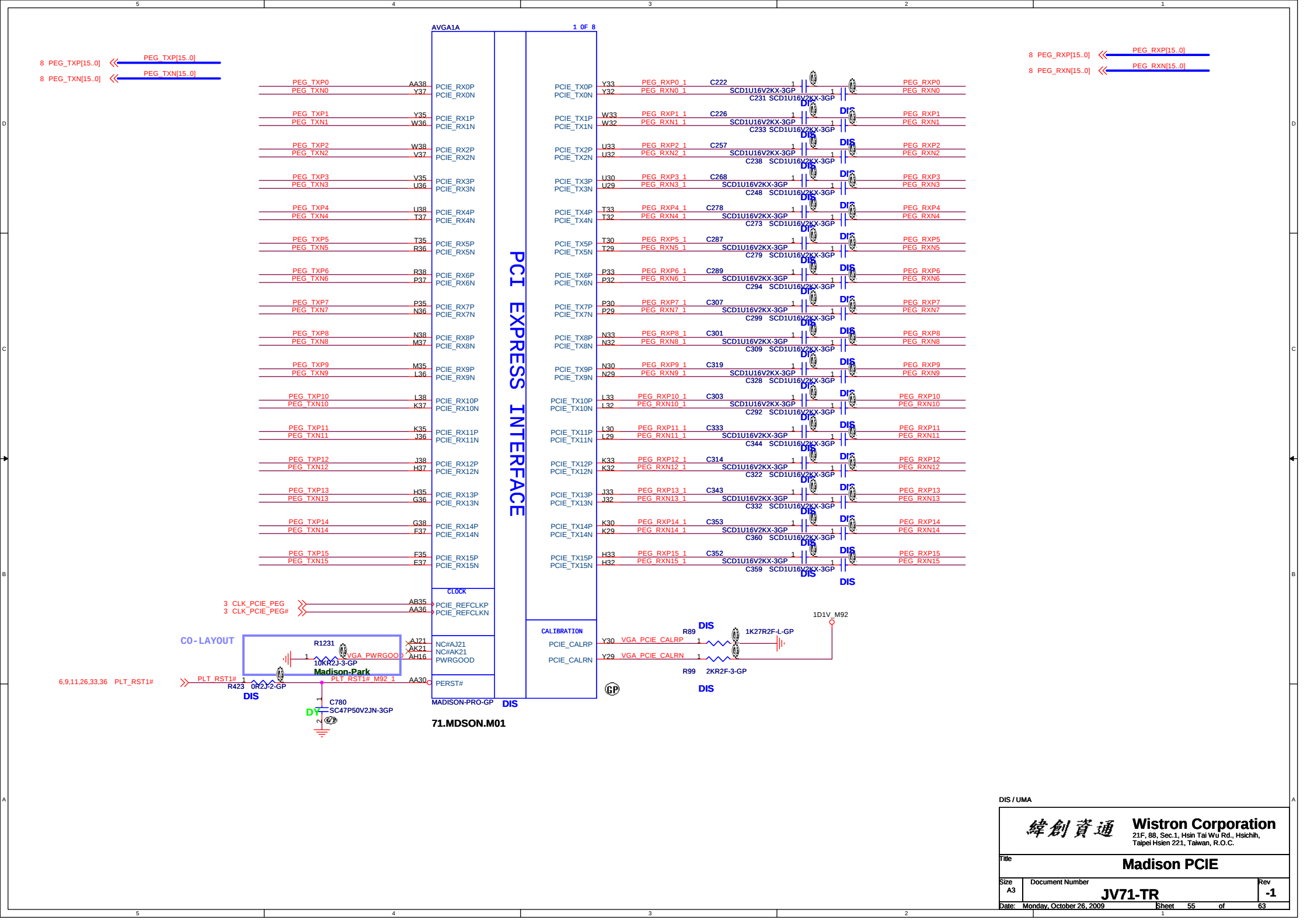
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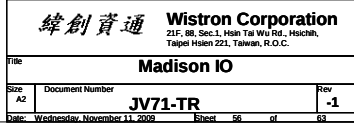
Rev

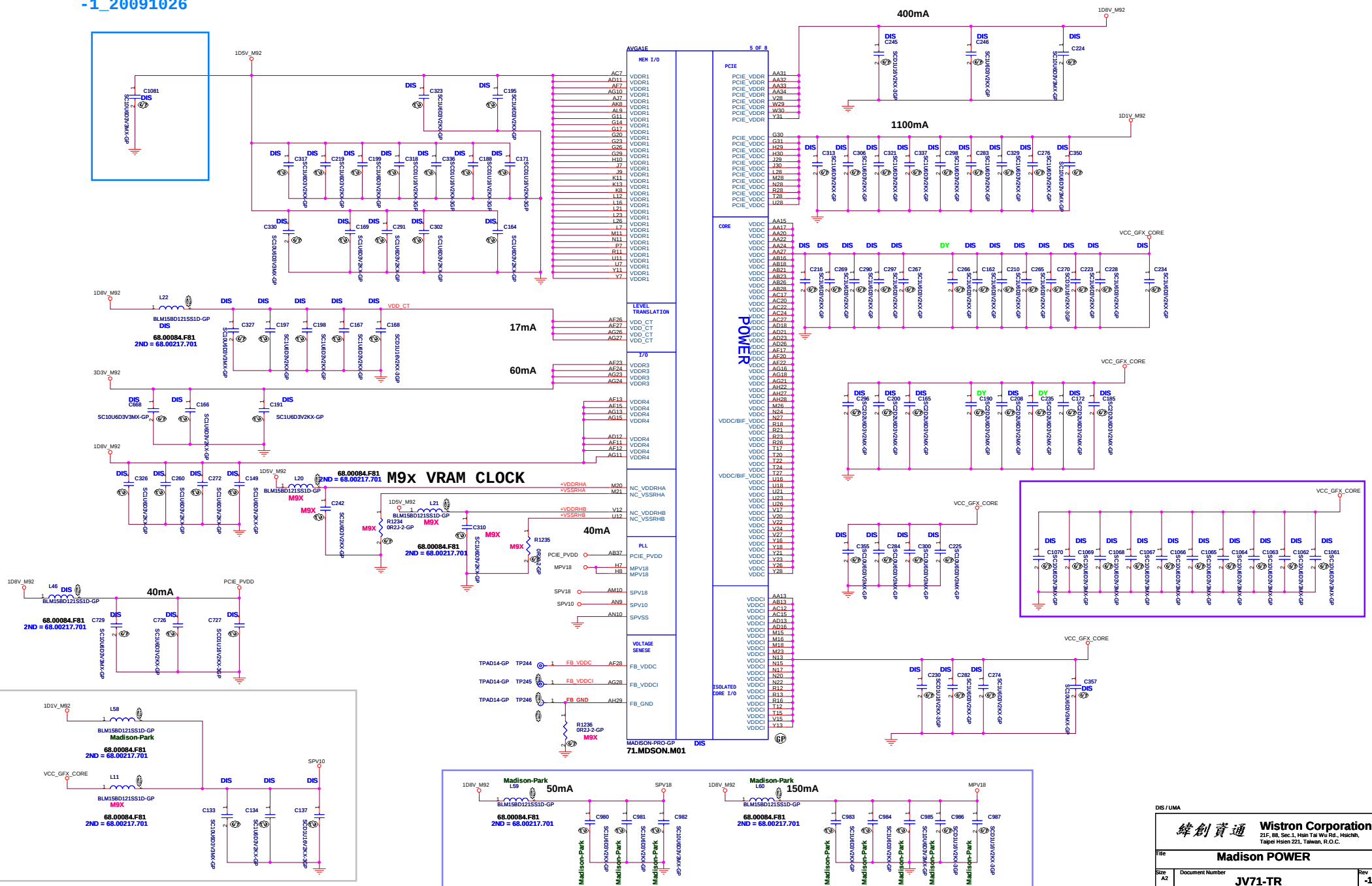
Thursday, November 12, 2009

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-1



[illegible]

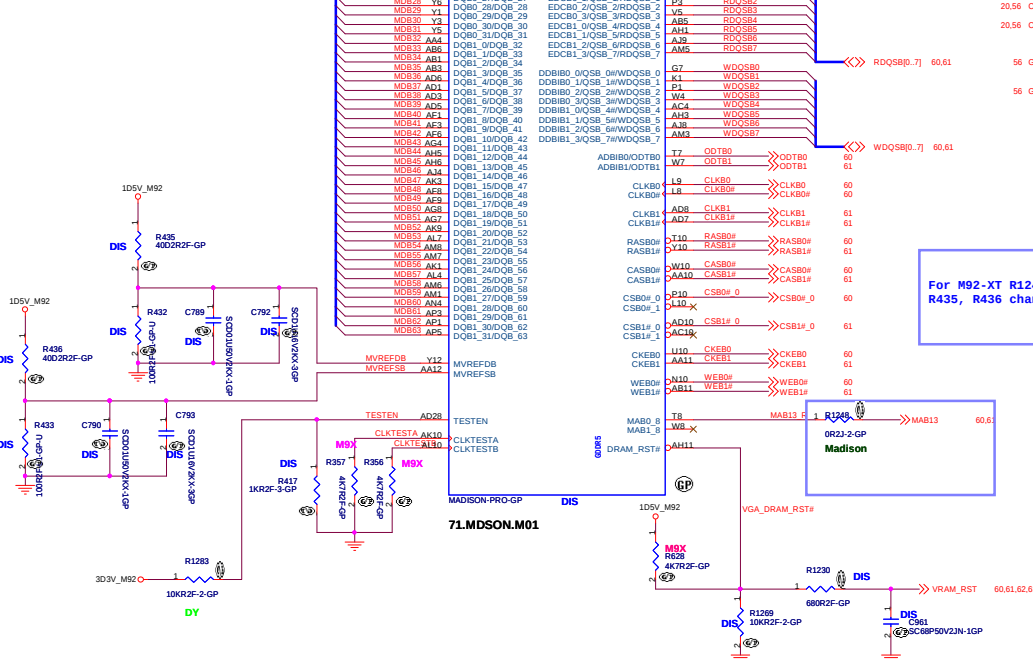
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For SSTL-1.8/SSTL-2/DDR1/GDDR1: 0.5 * VDDR1.
For DDR3/GDDR3/GDDR4/GDDR5: 0.7 * VDDR1.

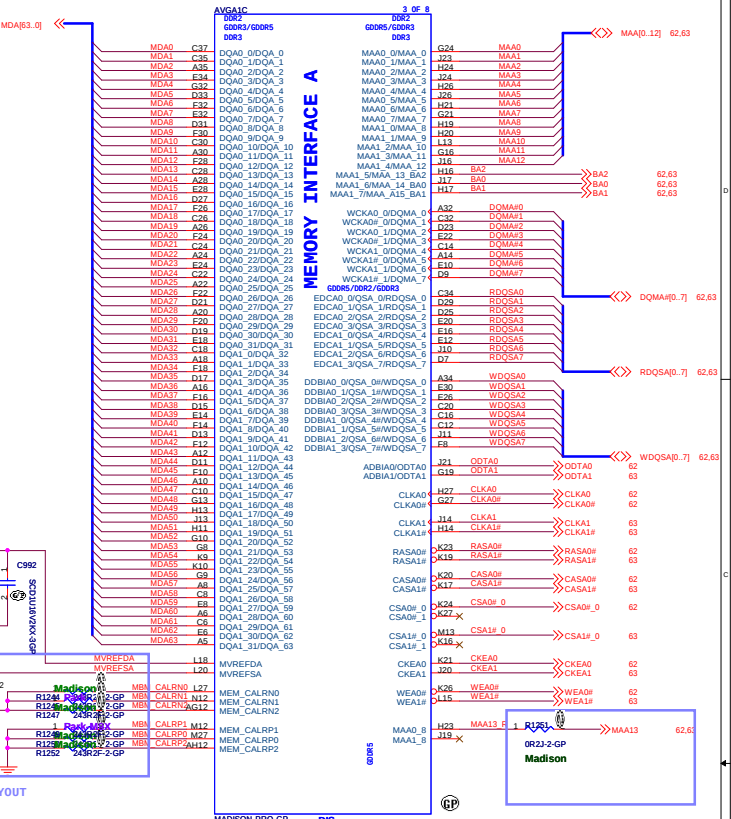
DIVIDER RESISTORS	GDDR5	GDDR3	DDR3
MVREF	1.5V	1.8/1.5V	1.5V
MVREF TO PWR	40.2R	40.2R	40.2R
MVREF TO GND	100R	100R	100R



STRAPS	PIN	DESCRIPTION	RECOMMENDED SETTINGS 0= DO NOT INSTALL RESISTOR 1= INSTALL 10K RESISTOR X= DESIGN DEPENDANT NA= NOT APPLICABLE
TX_PWRS_ENB (Internal PD)	GPIO0	PCIe FULL TX OUTPUT SWING Transmitter Power Savings Enable 0= 50% tx output swing 1= Full TX output swing	1
TX_DEEMPH_EN (Internal PD)	GPIO1	Transmitter de-emphasis Enable 0= Tx de-emphasis disabled 1= Tx de-emphasis enabled	1
BIF_GEN2_EN_A	GPIO2	PCIe GEN2 ENABLED 0 = Advertises the PCI-E device as 2.5GT/s 1 = Advertises the PCI-E device as 5GT/s	1
AC_BATT	GPIO5	AC (Performance mode) = 3.3 V Battery saving mode = 0.0 V	
ROMSO	GPIO8	BF CLK PM EN Serial ROM Output from ROM	0
ROMSI	GPIO9	VGA ENABLED Serial ROM Input to ROM	0
ROMIDCFG[3:0] (Internal PD)	GPIO[13,12,11]	SERIAL ROM TYPE OR MEMORY APERTURE SIZE SELECT if BIOS_ROM_EN=1, then Config[3:0] defines the ROM type if BIOS_ROM_EN=0, then Config[3:0] defines the primary memory aperture size	X X X

STRAPS	PIN	DESCRIPTION	RECOMMENDED SETTINGS 0= DO NOT INSTALL RESISTOR 1= INSTALL 10K RESISTOR X= DESIGN DEPENDANT NA= NOT APPLICABLE
PWRCTRL_[1,0]	GPIO[15,20]	Power control signals to control the core voltage regulator	
BB_EN	GPIO21	Back Bias (body bias) which minimizes power consumption in battery modes. 0V = Disable 3D3V = Enable	0
AUD[1] AUD[0] (Internal PD)	VGA_HSYNC VGA_VSYNC	AUD[1:0] 00: No audio function 01: Audio for DisplayPort and HDMI (If adapter is detected) 10: Audio for DisplayPort only 11: Audio for both DisplayPort and HDMI	1
CCBYPASS	GENERIC		0
GPIO	DVPPDATA[23:20] (Internal PD)	Initialization Behavior: This signal is input during reset (no reference clock is required). After reset, the default state is output low (0 V). The signals above can be left unconnected if not used.	

Designator	For M96-M2	For Mannheim	M92-M2
R_MEM_1	R628	4.7K	DY
R_MEM_2	R1230	0R	680R
R_MEM_3	R1269	4.7K	10K
C_MEM	C961	1nF	68pF



AMD RESERVED CONFIGURATION STRAPS			
ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET			
H2SYNCR, GENERIC			
PULLUP PADS ARE NOT REQUIRED FOR THESE STRAPS BUT IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET			
GPIO_28_TD0, GPIO21_BB_EN			

If BIOS_ROM_EN (GPIO22) = 0		If BIOS_ROM_EN (GPIO22) = 1	
Size of the Primary memory apertures	GPIO[13,12,11]	Manufacturer	Part Number
128MB	x000	ST Microelectronics	M25P05A
256MB	x001		M25P10A
512MB	x010		M25P20
1GB	x		M25P40
2GB	x	CH3815 (formerly PMC)	Pm25LV512A
4GB	x		Pm25LV010A

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File

Madison Memory / Straps

Size A2

Document Number

JV71-TR

Rev

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Date: Wednesday, November 11, 2009

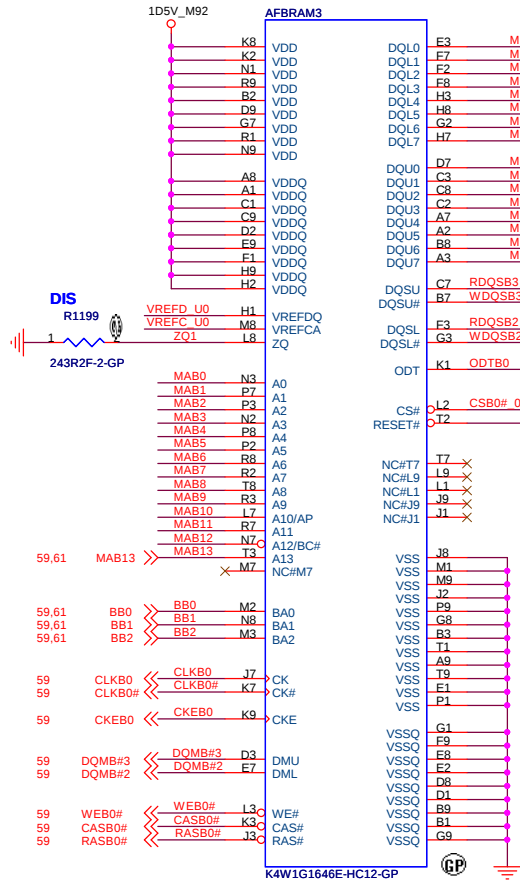
Sheet

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GDDR3



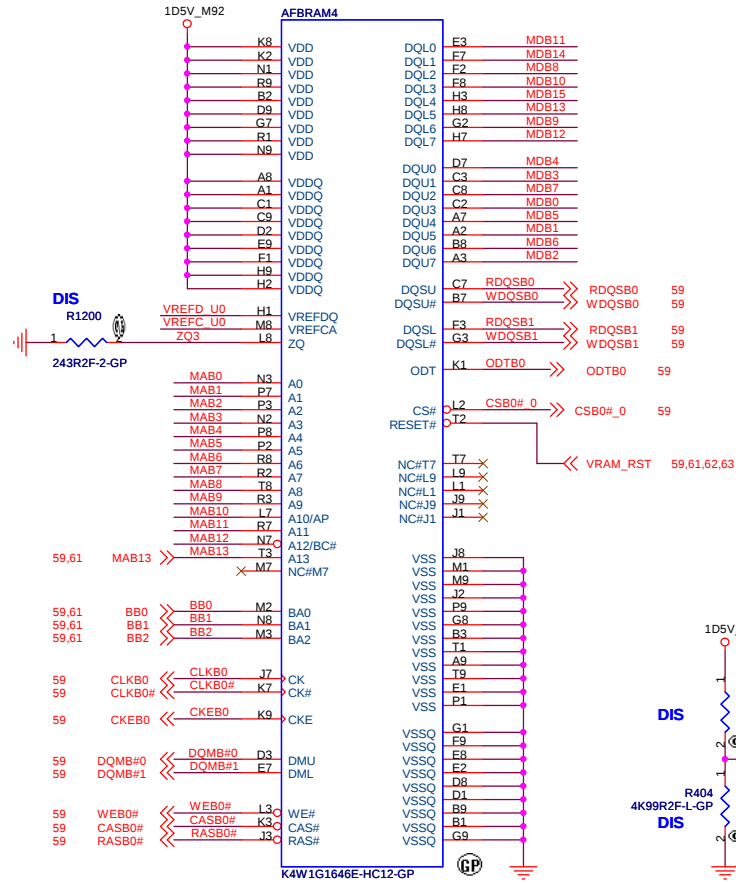
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2ND = 72.51G63.C0U

SAMSUNG 1ST=72.41164.H0U

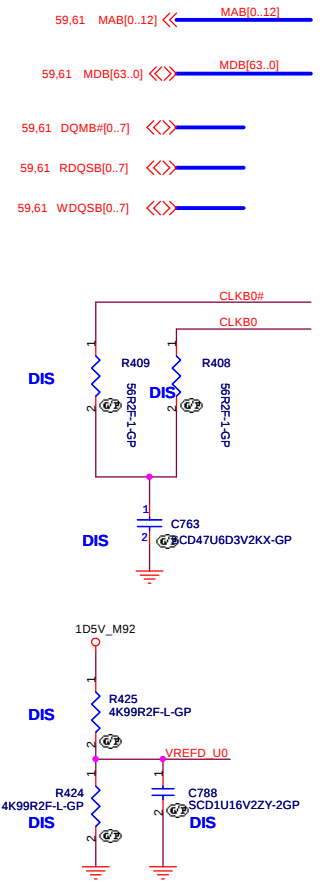
HYUNIX 2ND=72.51G63.C0U



DIS

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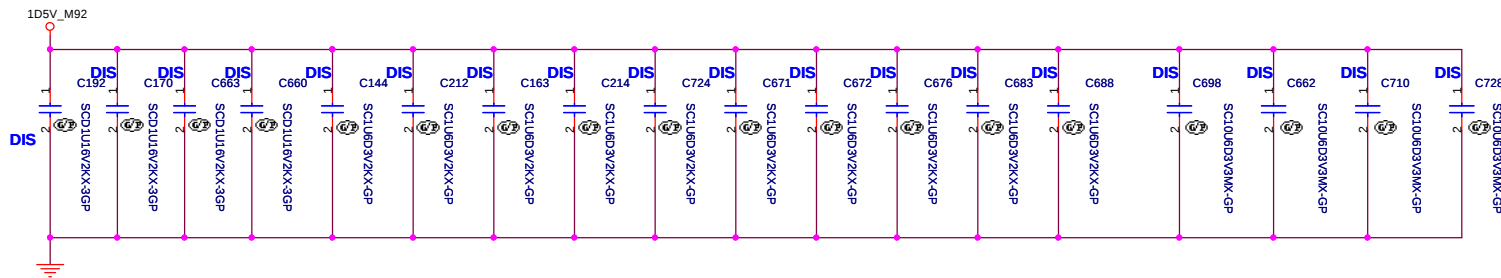
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DIS

72.41164.H0U

2ND = 72.51G63.C0U



DIS

72.41164.H0U

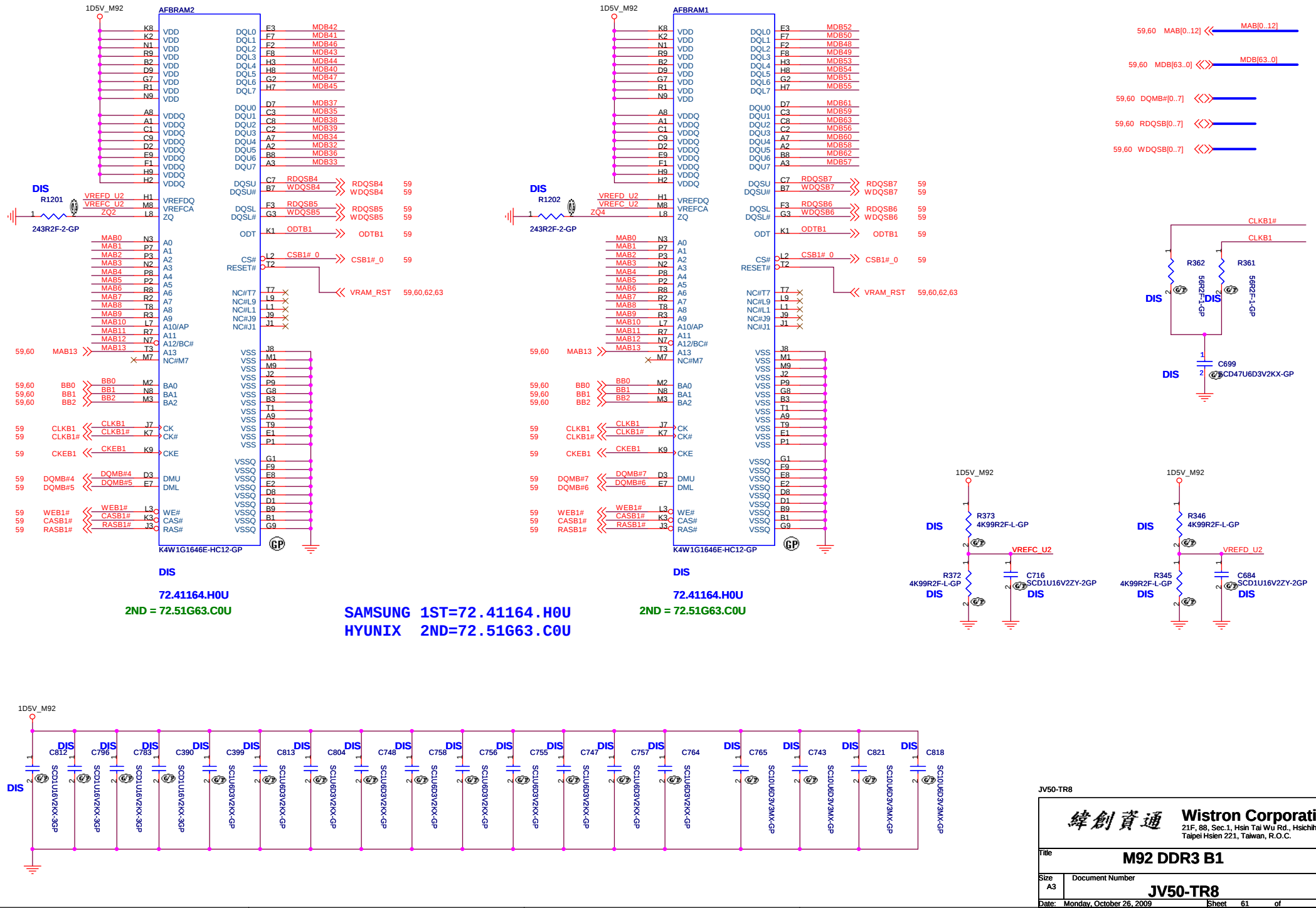
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JV50-TR8

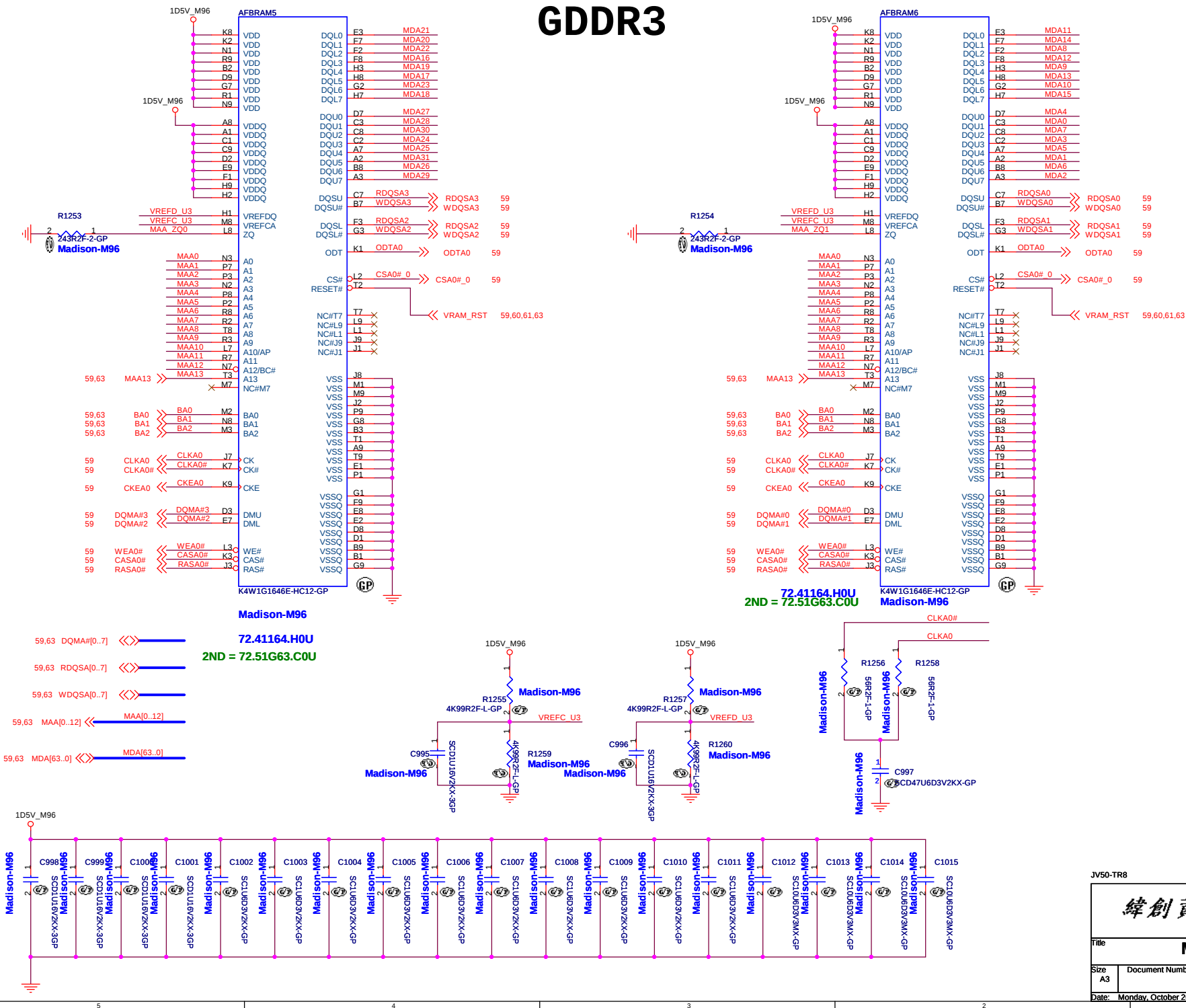
緯創資通 Wistron Corporation
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Title M92 DDR3 B0		
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GDDR3



GDDR3



GDDR3

